PCF2129 Accurate RTC with integrated quartz crystal for industrial applications Rev. 8.0 – 18 July 2022 Product data sheet

1 General description

The PCF2129 is a CMOS¹ Real Time Clock (RTC) and calendar with an integrated Temperature Compensated Crystal (Xtal) Oscillator (TCXO) and a 32.768 kHz quartz crystal optimized for very high accuracy and very low power consumption. The PCF2129 has a selectable I²C-bus or SPI-bus, a backup battery switch-over circuit, a programmable watchdog function, a timestamp function, and many other features.

For a selection of NXP Real-Time Clocks, see <u>Table 82</u>

2 Features and benefits

- UL Recognized Component (PCF2129AT and PCF2129T)
- Operating temperature range from -40 °C to +85 °C
- Temperature Compensated Crystal Oscillator (TCXO) with integrated capacitors
- Typical accuracy:
 - PCF2129AT: ±3 ppm from -15 °C to +60 °C
 - PCF2129T: ±3 ppm from -30 °C to +80 °C
- Integration of a 32.768 kHz quartz crystal and oscillator in the same package
- Provides year, month, day, weekday, hours, minutes, seconds, and leap year correction
- Timestamp function
 - with interrupt capability
 - detection of two different events on one multilevel input pin (for example, for tamper detection)
- Two line bidirectional 400 kHz Fast-mode I²C-bus interface
- Three line SPI-bus with separate data input and output (maximum speed 6.5 Mbit/s)
- · Battery backup input pin and switch-over circuitry
- · Battery backed output voltage
- · Battery low detection function
- Power-On Reset Override (PORO)
- Oscillator stop detection function
- Interrupt output (open-drain)
- Programmable 1 second or 1 minute interrupt
- Programmable watchdog timer with interrupt
- · Programmable alarm function with interrupt capability
- Programmable square output
- Clock operating voltage: 1.8 V to 4.2 V

¹ The definition of the abbreviations and acronyms used in this data sheet can be found in <u>Section 20</u>.



- Low supply current: typical 0.70 μ A at V_{DD} = 3.3 V

3 Applications

- · Electronic metering for electricity, water, and gas
- Precision timekeeping
- Access to accurate time of the day
- GPS equipment to reduce time to first fix
- Applications that require an accurate process timing
- · Products with long automated unattended operation time

4 Ordering information

Table 1. Ordering information

Type number	Topside marking	Package	Package							
		Name	Description	Version						
PCF2129AT	PCF2129AT	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1						
PCF2129T	PCF2129T	SO16	plastic small outline package; 16 leads; body width 7.5 mm	SOT162-1						

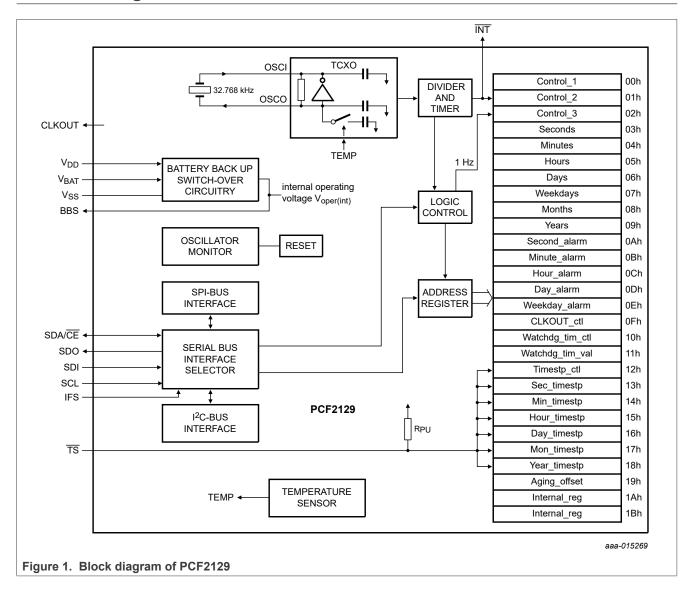
4.1 Ordering options

Table 2. Ordering options

Type number	Orderable part number	Package	Packing method ^[1]	Minimum order quantity	Temperature
PCF2129AT	PCF2129AT/2,518	SO20	reel 13" Q1 DP	2000	T _{amb} = -40 °C to +85 °C
PCF2129T	PCF2129T/2,518	SO16	reel 13" Q1 DP	1000	T _{amb} = -40 °C to +85 °C

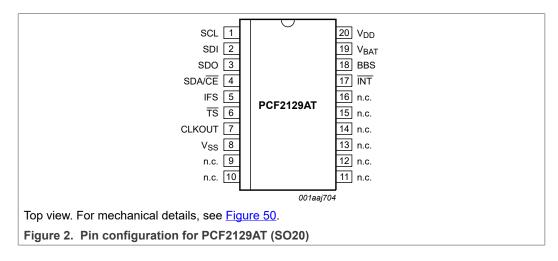
[1] Standard packing quantities and other packaging data are available at www.nxp.com/packages/.

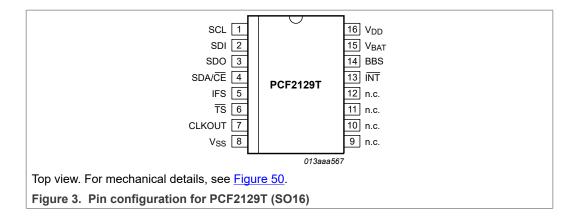
5 Block diagram

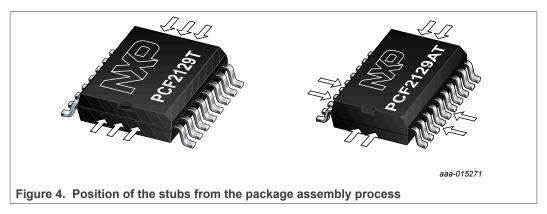


6 Pinning information

6.1 Pinning







After lead forming and cutting, there remain stubs from the package assembly process. These stubs are present at the edge of the package as illustrated in <u>Figure 4</u>. The stubs are at an electrical potential. To avoid malfunction of the PCF2129, it has to be ensured that they are not shorted with another electrical potential (e.g. by condensation).

6.2 Pin description

Table 3. Pin description of PCF2129

Input or input/output pins must always be at a defined level (V_{SS} or V_{DD}) unless otherwise specified.

Symbol	Pin		Description
	PCF2129AT	PCF2129T	
SCL	1	1	combined serial clock input for both I ² C-bus and SPI-bus
SDI	2	2	serial data input for SPI-bus connect to pin V _{SS} if I ² C-bus is selected
SDO	3	3	serial data output for SPI-bus, push-pull
SDA/CE	4	4	combined serial data input and output for the I ² C-bus and chip enable input (active LOW) for the SPI-bus
IFS	5	5	interface selector input connect to pin V _{SS} to select the SPI-bus connect to pin BBS to select the I ² C-bus
TS	6	6	timestamp input (active LOW) with 200 $k\Omega$ internal pull-up resistor ($R_{PU})$
CLKOUT	7	7	clock output (open-drain)
V _{SS}	8	8	ground supply voltage
n.c.	9 to 16	9 to 12	not connected; do not connect; do not use as feed through
INT	17	13	interrupt output (open-drain; active LOW)
BBS	18	14	output voltage (battery backed)
V _{BAT}	19	15	battery supply voltage (backup) connect to V _{SS} if battery switch over is not used
V _{DD}	20	16	supply voltage

7 Functional description

The PCF2129 is a Real Time Clock (RTC) and calendar with an on-chip Temperature Compensated Crystal (Xtal) Oscillator (TCXO) and a 32.768 kHz quartz crystal integrated into the same package (see <u>Section 7.3.3</u>).

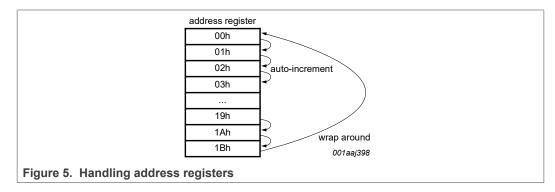
Address and data are transferred by a selectable 400 kHz Fast-mode I^2 C-bus or a 3 line SPI-bus with separate data input and output (see <u>Section 8</u>). The maximum speed of the SPI-bus is 6.5 Mbit/s.

The PCF2129 has a backup battery input pin and backup battery switch-over circuit which monitors the main power supply. The backup battery switch-over circuit automatically switches to the backup battery when a power failure condition is detected (see <u>Section 7.5.1</u>). Accurate timekeeping is maintained even when the main power supply is interrupted.

A battery low detection circuit monitors the status of the battery (see <u>Section 7.5.2</u>). When the battery voltage drops below a certain threshold value, a flag is set to indicate that the battery must be replaced soon. This ensures the integrity of the data during periods of battery backup.

7.1 Register overview

The PCF2129 contains an auto-incrementing address register: the built-in address register will increment automatically after each read or write of a data byte up to the register 1Bh. After register 1Bh, the auto-incrementing will wrap around to address 00h (see Figure 5).



- The first three registers (memory address 00h, 01h, and 02h) are used as control registers (see <u>Section 7.2</u>).
- The memory addresses 03h through to 09h are used as counters for the clock function (seconds up to years). The date is automatically adjusted for months with fewer than 31 days, including corrections for leap years. The clock can operate in 12-hour mode with an AM/PM indication or in 24-hour mode (see <u>Section 7.8</u>).
- The registers at addresses 0Ah through 0Eh define the alarm function. It can be selected that an interrupt is generated when an alarm event occurs (see <u>Section 7.9</u>).
- The register at address 0Fh defines the temperature measurement period and the clock out mode. The temperature measurement can be selected from every 4 minutes (default) down to every 30 seconds (see <u>Table 13</u>). CLKOUT frequencies of 32.768 kHz (default) down to 1 Hz for use as system clock, microcontroller clock, and so on, can be chosen (see <u>Table 14</u>).
- The registers at addresses 10h and 11h are used for the watchdog timer functions. The watchdog timer has four selectable source clocks allowing for timer periods from less than 1 ms to greater than 4 hours (see <u>Table 51</u>). An interrupt is generated when the watchdog times out.
- The registers at addresses 12h to 18h are used for the timestamp function. When the trigger event happens, the actual time is saved in the timestamp registers (see <u>Section 7.11</u>).
- The register at address 19h is used for the correction of the crystal aging effect (see <u>Section 7.4.1</u>).
- The registers at addresses 1Ah and 1Bh are for internal use only.
- The registers Seconds, Minutes, Hours, Days, Months, and Years are all coded in Binary Coded Decimal (BCD) format to simplify application use. Other registers are either bit-wise or standard binary.

When one of the RTC registers is written or read, the content of all counters is temporarily frozen. This prevents a faulty writing or reading of the clock and calendar during a carry condition (see <u>Section 7.8.8</u>).

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Accurate RTC with integrated quartz crystal for industrial applications

Table 4. Register overview

NXP Semiconductors

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as T must always be written with logic 0. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Address	Register name	Bit								Reset value	Reference
		7	6	5	4	3	2	1	0		
Control re	gisters										
00h	Control_1	EXT_ TEST	Т	STOP	TSF1	POR_ OVRD	12_24	MI	SI	0000 1000	Table 6
01h	Control_2	MSF	WDTF	TSF2	AF	Т	TSIE	AIE	Т	0000 0000	Table 8
02h	Control_3		PWRMNG[2:	0]	BTSE BF BLF BIE BLIE						Table 10
Time and	date registers	I				1	-1	1			
03h	Seconds	OSF			SE	CONDS (0 t	o 59)			1XXX XXXX	Table 21
04h	Minutes	-			MI	NUTES (0 to	- XXX XXXX	Table 24			
05h	Hours	-	-	AMPM	AMPM HOURS (1 to 12) in 12-hour mode						Table 26
					HOU	URS (0 to 23	XX XXXX				
06h	Days	-	-		DAYS (1 to 31)						Table 28
07h	Weekdays	-	-	-	-	-	WE	EKDAYS (0 to 6)	XXX	Table 30
08h	Months	-	-	-		M	ONTHS (1 to	o 12)		X XXXX	Table 33
09h	Years			-	YEARS	6 (0 to 99)				XXXX XXXX	Table 36
Alarm reg	isters	I									/
0Ah	Second_alarm	AE_S			SECO	ND_ALARM	(0 to 59)			1XXX XXXX	Table 38
0Bh	Minute_alarm	AE_M			MINU	TE_ALARM	(0 to 59)			1XXX XXXX	Table 40
0Ch	Hour_alarm	AE_H	-	AMPM	Н	OUR_ALAR	M (1 to 12) i	n 12-hour r	node	1 - XX XXXX	Table 42
					HOUR_	ALARM (0 t	o 23) in 24-h	our mode		1 - XX XXXX	
0Dh	Day_alarm	AE_D	-			DAY_ALA	RM (1 to 31)			1 - XX XXXX	Table 44
0Eh	Weekday_alarm	AE_W	-	-	-	-	WEEK	DAY_ALAF	RM (0 to 6)	1 XXX	Table 46
CLKOUT o	control register									•	
0Fh	CLKOUT_ctl	TCI	R[1:0]	OTPR	-	-		COF[2:0]	00X 000	Table 12

Table 4. Register overview...continued

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as T must always be written with logic 0. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Address	Register name	Bit								Reset value	Reference
		7	6	5	4	3	2	1	0		
Watchdog r	egisters										
10h	Watchdg_tim_ctl	WD_CD	Т	TI_TP	-	-	-	TF[[1:0]	000 11	Table 48
11h	Watchdg_tim_val			١	WATCHDG_	TIM_VAL[7:0)]			XXXX XXXX	Table 50
Timestamp	Timestamp registers										
12h	Timestp_ctl	TSM	TSOFF	-		1_0_	16_TIMEST		00 - X XXXX	Table 57	
13h	Sec_timestp	-			SECON	D_TIMESTP	(0 to 59)			- XXX XXXX	Table 59
14h	Min_timestp	-			MINUTE	E_TIMESTP	(0 to 59)			- XXX XXXX	Table 61
15h	Hour_timestp	-	-	AMPM	НО	UR_TIMES	ΓΡ (1 to 12)	in 12-hour m	ode	XX XXXX	Table 63
					HOUR_T	IMESTP (0 t	o 23) in 24-ł	nour mode		XX XXXX	
16h	Day_timestp	-	-			DAY_TIMES	STP (1 to 31)		XX XXXX	Table 65
17h	Mon_timestp	-	-	-		MONTH	I_TIMESTP	(1 to 12)		X XXXX	Table 67
18h	Year_timestp			Ň	YEAR_TIME	STP (0 to 99	9)			XXXX XXXX	Table 69
Aging offse	et register										
19h	Aging_offset	-	-	-	AO[3:0]						Table 16
Internal reg	isters										
1Ah	Internal_reg	-	-	-	-	-	-	-	-		-
1Bh	Internal_reg	-	-	-	-	-	-	-	-		-

7.2 Control registers

The first 3 registers of the PCF2129, with the addresses 00h, 01h, and 02h, are used as control registers.

7.2.1 Register Control_1

 Table 5. Control_1 - control and status register 1 (address 00h) bit allocation

 Bits labeled as T must always be written with logic 0.

Bit	7	6	5	4	3	2	1	0
Symbol	EXT_ TEST	Т	STOP	TSF1	POR_ OVRD	12_24	MI	SI
Reset value	0	0	0	0	1	0	0	0

 Table 6. Control_1 - control and status register 1 (address 00h) bit description

 Bits labeled as T must always be written with logic 0.

Bit	Symbol	Value	Description	Reference				
7	EXT_TEST	0	normal mode	Section 7.13				
		1	external clock test mode	-				
6	Т	0	unused	-				
5	STOP	0	RTC source clock runs					
		1	RTC clock is stopped; RTC divider chain flip-flops are asynchronously set logic 0; CLKOUT at 32.768 kHz, 16.384 kHz, or 8.192 kHz is still available	-				
4	TSF1	0	no timestamp interrupt generated	Section 7.11.1				
		1	flag set when TS input is driven to an intermediate level between power supply and ground; flag must be cleared to clear interrupt					
3	POR_OVRD	0	Power-On Reset Override (PORO) facility disabled; set logic 0 for normal operation	Section 7.7.2				
		1	Power-On Reset Override (PORO) sequence reception enabled					
2	12_24	0	24-hour mode selected	<u>Table 26,</u>				
		1	12-hour mode selected	<u>Table 42,</u> <u>Table 43,</u> <u>Table 63</u>				
1	MI	0	minute interrupt disabled	Section 7.12.1				
		1	minute interrupt enabled					
0	SI	0	second interrupt disabled					
		1	second interrupt enabled					

7.2.2 Register Control_2

Table 7. Control_2 - control and status register 2 (address 01h) bit allocation Bits labeled as T must always be written with logic 0.

Bit	7	6	5	4	3	2	1	0
Symbol	MSF	WDTF	TSF2	AF	Т	TSIE	AIE	Т
Reset value	0	0	0	0	0	0	0	0

Table 8. Control_2 - control and status register 2 (address 01h) bit description Bits labeled as T must always be written with logic 0.

Bit	Symbol	Value	Description	Reference
7	MSF	0	no minute or second interrupt generated	Section 7.12
		1	flag set when minute or second interrupt generated;	
			flag must be cleared to clear interrupt	
6	WDTF	0	no watchdog timer interrupt or reset generated	Section 7.12.3
		1	flag set when watchdog timer interrupt or reset generated;	
			flag cannot be cleared by command (read-only)	
5	TSF2	0	no timestamp interrupt generated	Section 7.11.1
		1	flag set when TS input is driven to ground; flag must be cleared to clear interrupt	
4	AF	0	no alarm interrupt generated	Section 7.9.6
		1	flag set when alarm triggered; flag must be cleared to clear interrupt	
3	Т	0	unused	-
2	TSIE	0	no interrupt generated from timestamp flag	Section 7.12.5
		1	interrupt generated when timestamp flag set	-
1	AIE	0	no interrupt generated from the alarm flag	Section 7.12.4
		1	interrupt generated when alarm flag set	
0	Т	0	unused	-
			1	

7.2.3 Register Control_3

Table 9. Control_3 - control and status register 3 (address 02h) bit allocation

Bit	7	6	5	4	3	2	1	0
Symbol	F	PWRMNG[2:0]]	BTSE	BF	BLF	BIE	BLIE
Reset value	0	0	0	0	0	0	0	0

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Bit	Symbol	Value	Description	Reference
7 to 5	PWRMNG[2:0]	see <u>Table 18</u>	control of the battery switch-over, battery low detection, and extra power fail detection functions	Section 7.5
4	BTSE	0	no timestamp when battery switch-over occurs	Section 7.11.4
		1	time-stamped when battery switch-over occurs	
3	BF	0	no battery switch-over interrupt generated	Section 7.5.1
		1	flag set when battery switch-over occurs; flag must be cleared to clear interrupt	[─] and Section 7.11.4
2	BLF	0	0 battery status ok; no battery low interrupt generated	
		1	battery status low; flag cannot be cleared by command	_
1	BIE	0	no interrupt generated from the battery flag (BF)	Section 7.12.6
		1	interrupt generated when BF is set	
0	BLIE	0	no interrupt generated from battery low flag (BLF)	Section 7.12.7
		1	interrupt generated when BLF is set	

 Table 10. Control_3 - control and status register 3 (address 02h) bit description

7.3 Register CLKOUT_ctl

 Table 11. CLKOUT_ctl - CLKOUT control register (address 0Fh) bit allocation

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	TCR	[1:0]	OTPR	-	-	COF[2:0]		
Reset value	0	0	Х	-	-	0	0	0

Table 12. CLKOUT_ctl - CLKOUT control register (address 0Fh) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Description
7 to 6	TCR[1:0]	see Table 13	temperature measurement period
5	OTPR	0	no OTP refresh
		1	OTP refresh performed
4 to 3	-	-	unused
2 to 0	COF[2:0]	see Table 14	CLKOUT frequency selection

7.3.1 Temperature compensated crystal oscillator

The frequency of tuning fork quartz crystal oscillators is temperature-dependent. In the PCF2129, the frequency deviation caused by temperature variation is corrected by adjusting the load capacitance of the crystal oscillator.

The load capacitance is changed by switching between two load capacitance values using a modulation signal with a programmable duty cycle. In order to compensate the spread of the quartz parameters every chip is factory calibrated.

The frequency accuracy can be evaluated by measuring the frequency of the square wave signal available at the output pin CLKOUT. However, the selection of f_{CLKOUT} = 32.768 kHz (default value) leads to inaccurate measurements. Accurate frequency measurement occurs when f_{CLKOUT} = 16.384 kHz or lower is selected (see <u>Table 14</u>).

7.3.1.1 Temperature measurement

The PCF2129 has a temperature sensor circuit used to perform the temperature compensation of the frequency. The temperature is measured immediately after poweron and then periodically with a period set by the temperature conversion rate TCR[1:0] in the register CLKOUT_ctl.

TCR[1:0]		Temperature measurement period
00	[1]	4 min
01		2 min
10		1 min
11		30 seconds

 Table 13.
 Temperature measurement period

[1] Default value.

7.3.2 OTP refresh

Each IC is calibrated during production and testing of the device. The calibration parameters are stored on EPROM cells called One Time Programmable (OTP) cells. It is recommended to process an OTP refresh once after the power is up and the oscillator is operating stable. The OTP refresh takes less than 100 ms to complete.

To perform an OTP refresh, bit OTPR has to be cleared (set to logic 0) and then set to logic 1 again.

7.3.3 Clock output

A programmable square wave is available at pin CLKOUT. Operation is controlled by the COF[2:0] control bits in register CLKOUT_ctl. Frequencies of 32.768 kHz (default) down to 1 Hz can be generated for use as system clock, microcontroller clock, charge pump input, or for calibrating the oscillator.

CLKOUT is an open-drain output and enabled at power-on. When disabled, the output is high-impedance.

COF[2:0]			Typical duty cycle ^[1]
000	[2][3]	32 768	60 : 40 to 40 : 60
001		16 384	50 : 50
010		8 192	50 : 50
011		4 096	50 : 50
100		2 048	50 : 50

 Table 14. CLKOUT frequency selection

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COF[2:0]	CLKOUT frequency (Hz)	Typical duty cycle ^[1]
101	1 024	50 : 50
110	1	50 : 50
111	CLKOUT = high-Z	-

[1] Duty cycle definition: % HIGH-level time : % LOW-level time.

[2] Default value.[3] The specified

The specified accuracy of the RTC can be only achieved with CLKOUT frequencies not equal to 32.768 kHz or if CLKOUT is disabled.

The duty cycle of the selected clock is not controlled, however, due to the nature of the clock generation all but the 32.768 kHz frequencies are 50 : 50.

7.4 Register Aging_offset

 Table 15. Aging_offset - crystal aging offset register (address 19h) bit allocation

 Bit positions labeled as - are not implemented and return 0 when read.

Bit	7	6	5	4	3	2	1	0
Symbol	-	-	-	-		AO[3:0]	
Reset value	-	-	-	-	1	0	0	0

Table 16. Aging_offset - crystal aging offset register (address 19h) bit description
Bit positions labeled as - are not implemented and return 0 when read.

Bit	Symbol	Value	Description
7 to 4	-	-	unused
3 to 0	AO[3:0]	see Table 17	aging offset value

7.4.1 Crystal aging correction

The PCF2129 has an offset register Aging_offset to correct the crystal aging effects².

The accuracy of the frequency of a quartz crystal depends on its aging. The aging offset adds an adjustment, positive or negative, in the temperature compensation circuit which allows correcting the aging effect.

At 25 °C, the aging offset bits allow a frequency correction of typically 1 ppm per AO[3:0] value, from -7 ppm to +8 ppm.

Table 17. Frequency correction at 25 °C, typical

AO[3:0]			ppm
Decimal	Binary		
0	0000		+8
1	0001		+7
2	0010		+6

2 For further information, refer to the application note [1].

 Table 17. Frequency correction at 25 °C, typical...continued

AO[3:0]		ppm	
Decimal	Binary		
3	0011		+5
4	0100		+4
5	0101		+3
6	0110		+2
7	0111		+1
8	1000	[1]	0
9	1001		-1
10	1010		-2
11	1011		-3
12	1100		-4
13	1101		-5
14	1110		-6
15	1111		-7

[1] Default value.

7.5 Power management functions

The PCF2129 has two power supplies:

 V_{DD}

the main power supply

V_{BAT}

the battery backup supply

Internally, the PCF2129 is operating with the internal operating voltage $V_{oper(int)}$ which is also available as V_{BBS} on the battery backed output voltage pin, BBS. Depending on the condition of the main power supply and the selected power management function, $V_{oper(int)}$ is either on the potential of V_{DD} or V_{BAT} (see Section 7.5.3).

Two power management functions are implemented:

Battery switch-over function

monitoring the main power supply V_{DD} and switching to V_{BAT} in case a power fail condition is detected (see <u>Section 7.5.1</u>).

Battery low detection function

monitoring the status of the battery, V_{BAT} (see <u>Section 7.5.2</u>).

The power management functions are controlled by the control bits PWRMNG[2:0] (see <u>Table 18</u>) in register Control_3 (see <u>Table 10</u>):

PWRMNG[2:0]		Function
000	[1]	battery switch-over function is enabled in standard mode; battery low detection function is enabled
001		battery switch-over function is enabled in standard mode; battery low detection function is disabled
010		battery switch-over function is enabled in standard mode; battery low detection function is disabled
011		battery switch-over function is enabled in direct switching mode; battery low detection function is enabled
100		battery switch-over function is enabled in direct switching mode; battery low detection function is disabled
101		battery switch-over function is enabled in direct switching mode; battery low detection function is disabled
111	[2]	battery switch-over function is disabled, only one power supply (V_{DD}) ; battery low detection function is disabled

 Table 18. Power management control bit description

[1] Default value.

[2] When the battery switch-over function is disabled, the PCF2129 works only with the power supply V_{DD} . V_{BAT} must be put to ground and the battery low detection function is disabled.

7.5.1 Battery switch-over function

The PCF2129 has a backup battery switch-over circuit which monitors the main power supply V_{DD} . When a power failure condition is detected, it automatically switches to the backup battery.

One of two operation modes can be selected:

Standard mode

the power failure condition happens when:

V_{DD} < V_{BAT} AND V_{DD} < V_{th(sw)bat}

 $V_{th(sw)bat}$ is the battery switch threshold voltage. Typical value is 2.5 V. The battery switch-over in standard mode works only for V_{DD} > 2.5 V

Direct switching mode

the power failure condition happens when $V_{DD} < V_{BAT}$. Direct switching from V_{DD} to V_{BAT} without requiring V_{DD} to drop below $V_{th(sw)bat}$

When a power failure condition occurs and the power supply switches to the battery, the following sequence occurs:

- 1. The battery switch flag BF (register Control_3) is set logic 1.
- An interrupt is generated if the control bit BIE (register Control_3) is enabled (see <u>Section 7.12.6</u>).
- 3. If the control bit BTSE (register Control_3) is logic 1, the timestamp registers store the time and date when the battery switch occurred (see <u>Section 7.11.4</u>).
- 4. The battery switch flag BF is cleared by command; it must be cleared to clear the interrupt.

The interface is disabled in battery backup operation:

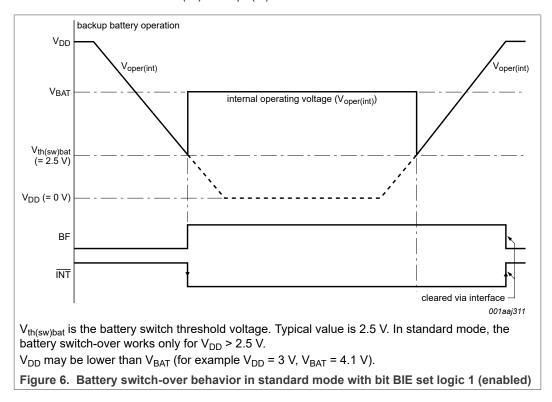
- Interface inputs are not recognized, preventing extraneous data being written to the device
- Interface outputs are high-impedance

For further information about I^2C -bus communication and battery backup operation, see <u>Section 8.3</u>.

7.5.1.1 Standard mode

If $V_{DD} > V_{BAT}$ OR $V_{DD} > V_{th(sw)bat}$: $V_{oper(int)}$ is at V_{DD} potential.

If V_{DD} < V_{BAT} AND V_{DD} < V_{th(sw)bat}: V_{oper(int)} is at V_{BAT} potential.



7.5.1.2 Direct switching mode

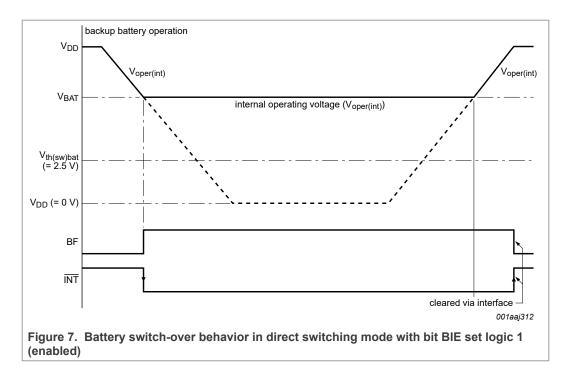
If $V_{DD} > V_{BAT}$: $V_{oper(int)}$ is at V_{DD} potential.

If $V_{DD} < V_{BAT}$: $V_{oper(int)}$ is at V_{BAT} potential.

The direct switching mode is useful in systems where V_{DD} is always higher than V_{BAT}. This mode is not recommended if the V_{DD} and V_{BAT} values are similar (for example, V_{DD} = 3.3 V, V_{BAT} \ge 3.0 V). In direct switching mode, the power consumption is reduced compared to the standard mode because the monitoring of V_{DD} and V_{th(sw)bat} is not performed.

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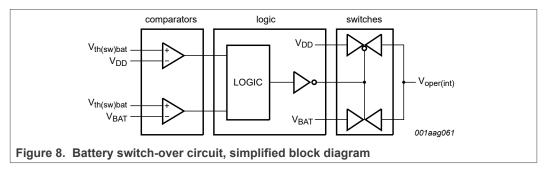
7.5.1.3 Battery switch-over disabled: only one power supply (V_{DD})

When the battery switch-over function is disabled:

- The power supply is applied on the V_{DD} pin
- The V_{BAT} pin must be connected to ground
- V_{oper(int)} is at V_{DD} potential
- The battery flag (BF) is always logic 0

7.5.1.4 Battery switch-over architecture

The architecture of the battery switch-over circuit is shown in Figure 8.



 $V_{oper(int)}$ is at V_{DD} or V_{BAT} potential.

Remark: It has to be assured that there are decoupling capacitors on the pins $V_{\text{DD}},\,V_{\text{BAT}},\,$ and BBS.

7.5.2 Battery low detection function

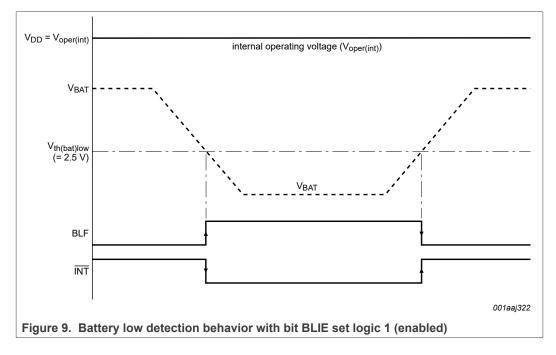
The PCF2129 has a battery low detection circuit which monitors the status of the battery $V_{\text{BAT}}.$

When V_{BAT} drops below the threshold value $V_{th(bat)low}$ (typically 2.5 V), the BLF flag (register Control_3) is set to indicate that the battery is low and that it must be replaced. Monitoring of the battery voltage also occurs during battery operation.

An unreliable battery cannot prevent that the supply voltage drops below V_{low} (typical 1.2 V) and with that the data integrity gets lost. (For further information about V_{low} see <u>Section 7.6</u>.)

When V_{BAT} drops below the threshold value $V_{th(bat)low}$, the following sequence occurs (see Figure 9):

- 1. The battery low flag BLF is set logic 1.
- 2. An interrupt is generated if the control bit BLIE (register Control_3) is enabled (see <u>Section 7.12.7</u>).
- 3. The flag BLF remains logic 1 until the battery is replaced. BLF cannot be cleared by command. It is automatically cleared by the battery low detection circuit when the battery is replaced or when the voltage rises again above the threshold value. This could happen if a super capacitor is used as a backup source and the main power is applied again.



7.5.3 Battery backup supply

The V_{BBS} voltage on the output pin BBS is at the same potential as the internal operating voltage $V_{oper(int)}$, depending on the selected battery switch-over function mode:

Battery switch-over function mode	Conditions	Potential of V _{oper(int)} and V _{BBS}
standard	$V_{DD} > V_{BAT} OR V_{DD} > V_{th(sw)bat}$	V _{DD}
	V _{DD} < V _{BAT} AND V _{DD} < V _{th(sw)bat}	V _{BAT}
direct switching	V _{DD} > V _{BAT}	V _{DD}

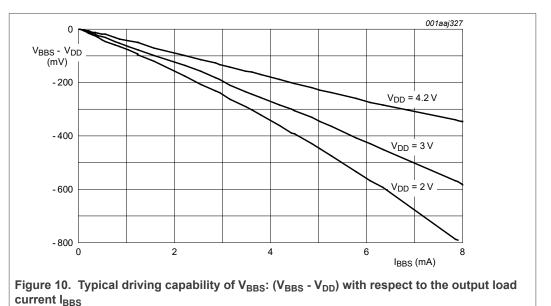
Table 19. Output pin BBS

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 Table 19. Output pin BBS...continued

Battery switch-over function mode	Conditions	Potential of V _{oper(int)} and V _{BBS}
	V _{DD} < V _{BAT}	V _{BAT}
disabled	only V _{DD} available, V _{BAT} must be put to ground	V _{DD}

The output pin BBS can be used as a supply for external devices with battery backup needs, such as SRAM (see [1]). For this case, <u>Figure 10</u> shows the typical driving capability when V_{BBS} is driven from V_{DD} .



7.6 Oscillator stop detection function

The PCF2129 has an on-chip oscillator detection circuit which monitors the status of the oscillation: whenever the oscillation stops, a reset occurs and the oscillator stop flag OSF (in register Seconds) is set logic 1.

• Power-on:

- 1. The oscillator is not running, the chip is in reset (OSF is logic 1).
- 2. When the oscillator starts running and is stable after power-on, the chip exits from reset.
- 3. The flag OSF is still logic 1 and can be cleared (OSF set logic 0) by command.

• Power supply failure:

- 1. When the power supply of the chip drops below a certain value (V_{low}), typically 1.2 V, the oscillator stops running and a reset occurs.
- 2. When the power supply returns to normal operation, the oscillator starts running again, the chip exits from reset.
- 3. The flag OSF is still logic 1 and can be cleared (OSF set logic 0) by command.

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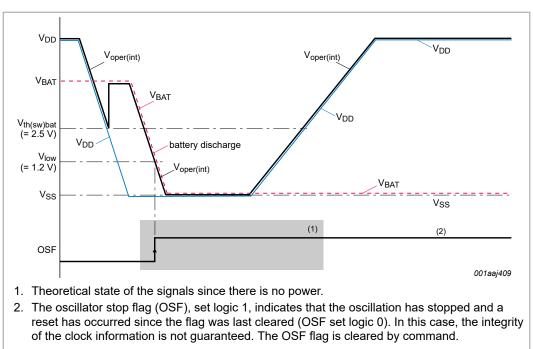


Figure 11. Power failure event due to battery discharge: reset occurs

7.7 Reset function

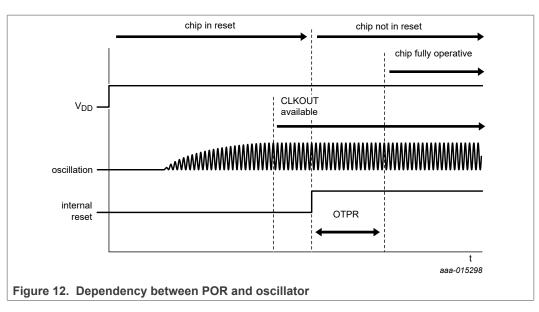
The PCF2129 has a Power-On Reset (POR) and a Power-On Reset Override (PORO) function implemented.

7.7.1 Power-On Reset (POR)

The POR is active whenever the oscillator is stopped. The oscillator is considered to be stopped during the time between power-on and stable crystal resonance (see Figure 12). This time may be in the range of 200 ms to 2 s depending on temperature and supply voltage. Whenever an internal reset occurs, the oscillator stop flag is set (OSF set logic 1).

The OTP refresh (see <u>Section 7.3.2</u>) should ideally be executed as the first instruction after start-up and also after a reset due to an oscillator stop.





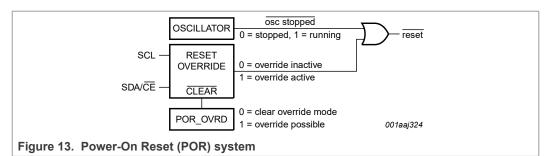
After POR, the following mode is entered:

- 32.768 kHz CLKOUT active
- Power-On Reset Override (PORO) available to be set
- 24-hour mode is selected
- · Battery switch-over is enabled
- · Battery low detection is enabled

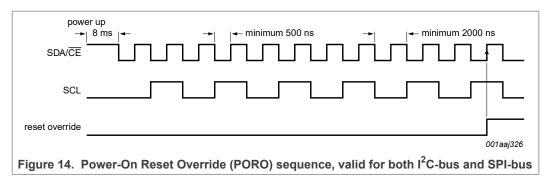
The register values after power-on are shown in <u>Table 4</u>.

7.7.2 Power-On Reset Override (PORO)

The POR duration is directly related to the crystal oscillator start-up time. Due to the long start-up times experienced by these types of circuits, a mechanism has been built in to disable the POR and therefore speed up the on-board test of the device.



The setting of the PORO mode requires that POR_OVRD in register Control_1 is set logic 1 and that the signals at the interface pins SDA/CE and SCL are toggled as illustrated in Figure 14. All timings shown are required minimum.



Once the override mode is entered, the device is immediately released from the reset state and the set-up operation can commence.

The PORO mode is cleared by writing logic 0 to POR_OVRD. POR_OVRD must be logic 1 before a re-entry into the override mode is possible. Setting POR_OVRD logic 0 during normal operation has no effect except to prevent accidental entry into the PORO mode.

7.8 Time and date function

Most of these registers are coded in the Binary Coded Decimal (BCD) format.

7.8.1 Register Seconds

Table 20. Seconds - seconds and clock integrity register (address 03h) bit allocation Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0		
Symbol	OSF		SECONDS (0 to 59)							
Reset value	1	Х	Х	Х	Х	Х	Х	X		

 Table 21. Seconds - seconds and clock integrity register (address 03h) bit description

 Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	OSF	0	-	clock integrity is guaranteed
		1	-	clock integrity is not guaranteed: oscillator has stopped and chip reset has occurred since flag was last cleared
6 to 4	SECONDS	0 to 5	ten's place	actual seconds coded in BCD format
3 to 0		0 to 9	unit place	

Table 22. Seconds coded in BCD format

	Upper-digit	t (ten's plac	e)	Digit (unit place)				
value in decimal	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
00	0	0	0	0	0	0	0	

Seconds	Upper-di	git (ten's pl	ace)	Digit (ur	Digit (unit place)					
value in decimal	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
01	0	0	0	0	0	0	1			
02	0	0	0	0	0	1	0			
:	:	:	:	:	:	:	:			
09	0	0	0	1	0	0	1			
10	0	0	1	0	0	0	0			
:	:	:	:	:	:	:	:			
58	1	0	1	1	0	0	0			
59	1	0	1	1	0	0	1			

Table 22. Seconds coded in BCD format...continued

7.8.2 Register Minutes

 Table 23. Minutes - minutes register (address 04h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0		
Symbol	-		MINUTES (0 to 59)							
Reset value	-	Х	Х	Х	Х	Х	Х	X		

Table 24. Minutes - minutes register (address 04h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	-	-	-	unused
6 to 4	MINUTES	0 to 5	ten's place	actual minutes coded in BCD format
3 to 0		0 to 9	unit place	

7.8.3 Register Hours

 Table 25. Hours - hours register (address 05h) bit allocation

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0	
Symbol	-	-	AMPM HOURS (1 to 12) in 12-hour mode						
			HOURS (0 to 23) in 24-hour mode						
Reset value	-	-	Х	X X X X X X					

Table 26. Hours - hours register (address 05h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 6	-	-	-	unused
12-hour mod	le ^[1]			
5	АМРМ	0	-	indicates AM
		1	-	indicates PM
4	HOURS	0 to 1	ten's place	actual hours coded in BCD format when in 12-hour
3 to 0		0 to 9	unit place	mode
24-hour mod	le ^[1]			
5 to 4	HOURS	0 to 2	ten's place	actual hours coded in BCD format when in 24-hour
3 to 0		0 to 9	unit place	mode

[1] Hour mode is set by the bit 12_24 in register Control_1 (see <u>Table 6</u>).

7.8.4 Register Days

Table 27. Days - days register (address 06h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0		
Symbol	-	-		DAYS (1 to 31)						
Reset value	-	-	Х	X X X X X X						

Table 28. Days - days register (address 06h) bit description

Bit	Symbol	Value	Place value	Description
7 to 6	-	-	-	unused
5 to 4	DAYS ^[1]	0 to 3	ten's place	actual day coded in BCD format
3 to 0		0 to 9	unit place	

[1] If the year counter contains a value which is exactly divisible by 4, including the year 00, the RTC compensates for leap years by adding a 29th day to February.

7.8.5 Register Weekdays

 Table 29. Weekdays - weekdays register (address 07h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	-	-	-	-	-	WEEKDAYS (0 to 6)		
Reset value	-	-	-	-	-	X X X		X

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Table 30. Weekdays - weekdays register (address 07h) bit description Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Description	
7 to 3	-	-	unused	
2 to 0	WEEKDAYS	0 to 6	actual weekday value, see <u>Table 31</u>	

Although the association of the weekdays counter to the actual weekday is arbitrary, the PCF2129 assumes that Sunday is 000 and Monday is 001 for the purpose of determining the increment for calendar weeks.

 Table 31. Weekday assignments

Day ^[1]	Bit							
	2	1	0					
Sunday	0	0	0					
Monday	0	0	1					
Tuesday	0	1	0					
Wednesday	0	1	1					
Thursday	1	0	0					
Friday	1	0	1					
Saturday	1	1	0					

[1] Definition may be reassigned by the user.

7.8.6 Register Months

 Table 32. Months - months register (address 08h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	-	-	-		MC	ONTHS (1 to 1	2)	
Reset value	-	-	-	Х	Х	Х	Х	Х

 Table 33. Months - months register (address 08h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 5	-	-	-	unused
4	MONTHS	0 to 1	ten's place	actual month coded in BCD format, see <u>Table 34</u>
3 to 0		0 to 9	unit place	

Month	Upper-digit (ten's place)	Digit (unit pla	Digit (unit place)						
	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
January	0	0	0	0	1				
February	0	0	0	1	0				
March	0	0	0	1	1				
April	0	0	1	0	0				
Мау	0	0	1	0	1				
June	0	0	1	1	0				
July	0	0	1	1	1				
August	0	1	0	0	0				
September	0	1	0	0	1				
October	1	0	0	0	0				
November	1	0	0	0	1				
December	1	0	0	1	0				

Table 34. Month assignments in BCD format

7.8.7 Register Years

Table 35. Years - years register (address 09h) bit allocation

Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol				YEARS	(0 to 99)			
Reset value	Х	Х	Х	Х	Х	Х	Х	X

Table 36. Years - years register (address 09h) bit description

Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 4	YEARS	0 to 9	ten's place	actual year coded in BCD format
3 to 0		0 to 9	unit place	

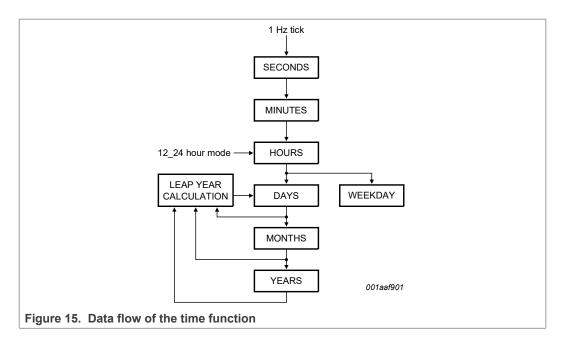
7.8.8 Setting and reading the time

Figure 15 shows the data flow and data dependencies starting from the 1 Hz clock tick.

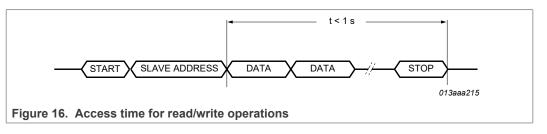
During read/write operations, the time counting circuits (memory locations 03h through 09h) are blocked.

This prevents

- Faulty reading of the clock and calendar during a carry condition
- Incrementing the time registers during the read cycle



After this read/write access is completed, the time circuit is released again. Any pending request to increment the time counters that occurred during the read/write access is serviced. A maximum of 1 request can be stored; therefore, all accesses must be completed within 1 second (see Figure 16).

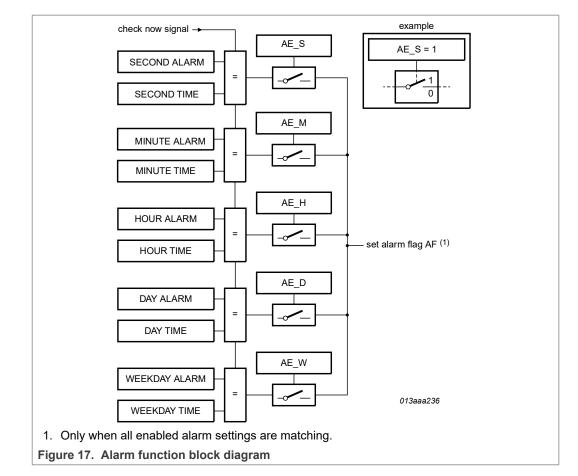


As a consequence of this method, it is very important to make a read or write access in one go. That is, setting or reading seconds through to years should be made in one single access. Failing to comply with this method could result in the time becoming corrupted.

As an example, if the time (seconds through to hours) is set in one access and then in a second access the date is set, it is possible that the time may increment between the two accesses. A similar problem exists when reading. A roll-over may occur between reads thus giving the minutes from one moment and the hours from the next. Therefore it is advised to read all time and date registers in one access.

7.9 Alarm function

When one or more of the alarm bit fields are loaded with a valid second, minute, hour, day, or weekday and its corresponding alarm enable bit (AE_x) is logic 0, then that information is compared with the actual second, minute, hour, day, and weekday (see Figure 17).



The generation of interrupts from the alarm function is described in Section 7.12.4.

7.9.1 Register Second_alarm

Table 37. Second_alarm - second alarm register (address 0Ah) bit allocationBits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	AE_S			SECO	ND_ALARM (() to 59)		
Reset value	1	Х	Х	Х	Х	Х	Х	Х

Table 38. Second_alarm - second alarm register (address 0Ah) bit description

Bit	Symbol	Value	Place value	Description
7	AE_S	0	-	second alarm is enabled
		1	-	second alarm is disabled
6 to 4	SECOND_ALARM	0 to 5	ten's place	second alarm information coded in BCD format
3 to 0		0 to 9	unit place	

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7.9.2 Register Minute_alarm

Table 39. Minute_alarm - minute alarm register (address 0Bh) bit allocationBits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	AE_M			MINUT	TE_ALARM (0	to 59)		
Reset value	1	Х	Х	Х	Х	Х	Х	Х

 Table 40. Minute_alarm - minute alarm register (address 0Bh) bit description

 Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	AE_M	0	-	minute alarm is enabled
		1	-	minute alarm is disabled
6 to 4	MINUTE_ALARM	0 to 5	ten's place	minute alarm information coded in BCD format
3 to 0		0 to 9	unit place	

7.9.3 Register Hour_alarm

Table 41. Hour_alarm - hour alarm register (address 0Ch) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	AE_H	-	AMPM HOUR_ALARM (1 to 12) in 12-hour mode					
				HOUR	_ALARM (0 to	23) in 24-hou	r mode	
Reset value	1	-	Х	Х	Х	Х	Х	Х

Table 42. Hour_alarm - hour alarm register (address 0Ch) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	AE_H		-	hour alarm is enabled
		1	-	hour alarm is disabled
6	-	-	-	unused
12-hour mod	le ^[1]			
5	АМРМ	0	-	indicates AM
		1	-	indicates PM
4	HOUR_ALARM	0 to 1	ten's place	hour alarm information coded in BCD format when in
3 to 0	-	0 to 9	unit place	12-hour mode
24-hour mod	le ^[1]			

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 Table 42. Hour_alarm - hour alarm register (address 0Ch) bit description...continued

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
5 to 4	HOUR_ALARM	0 to 2	ten's place	hour alarm information coded in BCD format when in
3 to 0		0 to 9	unit place	24-hour mode

[1] Hour mode is set by the bit 12_24 in register Control_1.

7.9.4 Register Day_alarm

 Table 43. Day_alarm - day alarm register (address 0Dh) bit allocation

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	AE_D	-	DAY_ALARM (1 to 31)					
Reset value	1	-	Х	Х	Х	Х	Х	Х

Table 44. Day_alarm - day alarm register (address 0Dh) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	AE_D	0	-	day alarm is enabled
		1	-	day alarm is disabled
6	-	-	-	unused
5 to 4	DAY_ALARM	0 to 3	ten's place	day alarm information coded in BCD format
3 to 0		0 to 9	unit place	

7.9.5 Register Weekday_alarm

Table 45. Weekday_alarm - weekday alarm register (address 0Eh) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	AE_W	-	-	-	-	WEEK	DAY_ALARM	(0 to 6)
Reset value	1	-	-	-	-	Х	Х	Х

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 Table 46. Weekday_alarm - weekday alarm register (address 0Eh) bit description

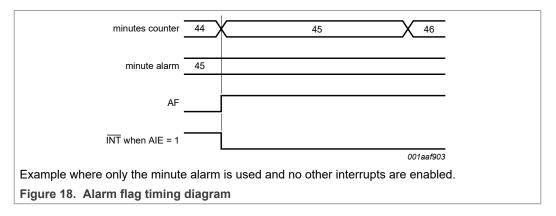
 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Description	
7	AE_W	0	weekday alarm is enabled	
		1	weekday alarm is disabled	
6 to 3	-	-	unused	
2 to 0	WEEKDAY_ALARM	0 to 6	weekday alarm information	

7.9.6 Alarm flag

When all enabled comparisons first match, the alarm flag AF (register Control_2) is set. AF remains set until cleared by command. Once AF has been cleared, it will only be set again when the time increments to match the alarm condition once more. For clearing the flags, see <u>Section 7.10.5</u>

Alarm registers which have their alarm enable bit AE_x at logic 1 are ignored.



7.10 Timer functions

The PCF2129 has a watchdog timer function. The timer can be switched on and off by using the control bit WD_CD in the register Watchdg_tim_ctl.

The watchdog timer has four selectable source clocks. It can, for example, be used to detect a microcontroller with interrupt and reset capability which is out of control (see Section 7.10.3)

To control the timer function and timer output, the registers Control_2, Watchdg_tim_ctl, and Watchdg_tim_val are used.

7.10.1 Register Watchdg_tim_ctl

Table 47. Watchdg_tim_ctl - watchdog timer control register (address 10h) bit allocationBit positions labeled as - are not implemented and return 0 when read. Bits labeled as T must always be written with logic 0.

Bit	7	6	5	4	3	2	1	0
Symbol	WD_CD	Т	TI_TP	-	-	-	TF[1:0]
Reset value	0	0	0	-	-	-	1	1

Bit	Symbol	Value	Description
7	WD_CD	0	watchdog timer disabled
		1	watchdog timer enabled; the interrupt pin INT is activated when timed out
6	Т	0	unused
5	TI_TP	0	the interrupt pin INT is configured to generate a permanent active signal when MSF is set
		1	the interrupt pin \overline{INT} is configured to generate a pulsed signal when MSF flag is set (see Figure 21)
4 to 2	-	-	unused
1 to 0	TF[1:0]		timer source clock for watchdog timer
		00	4.096 kHz
		01	64 Hz
		10	1 Hz
		11	1/ ₆₀ Hz

 Table 48. Watchdg_tim_ctl - watchdog timer control register (address 10h) bit description

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as T must always be written with logic 0.

7.10.2 Register Watchdg_tim_val

 Table 49. Watchdg_tim_val - watchdog timer value register (address 11h) bit allocation

 Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol		WATCHDG_TIM_VAL[7:0]						
Reset value	Х	Х	Х	Х	Х	Х	Х	Х

 Table 50. Watchdg_tim_val - watchdog timer value register (address 11h) bit description

 Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Description
7 to 0	WATCHDG_TIM_ VAL[7:0]		timer period in seconds: $TimerPeriod = \frac{n}{SourceClockFrequency}$ where n is the timer value

Table 51. Programmable watchdog timer

TF[1:0]	Timer source clock frequency	Units	Minimum timer period (n = 1)	Units	Maximum timer period (n = 255)	Units
00	4.096	kHz	244	μs	62.256	ms
01	64	Hz	15.625	ms	3.984	s
10	1	Hz	1	s	255	s

Table 51. Programmable	watchdog	timercontinued
------------------------	----------	----------------

	Timer source clock frequency		Minimum timer period (n = 1)		Maximum timer period (n = 255)	Units
11	1/60	Hz	60	s	15 300	S

7.10.3 Watchdog timer function

The watchdog timer function is enabled or disabled by the WD_CD bit of the register Watchdg_tim_ctl (see <u>Table 48</u>).

The 2 bits TF[1:0] in register Watchdg_tim_ctl determine one of the four source clock frequencies for the watchdog timer: 4.096 kHz, 64 Hz, 1 Hz, or $\frac{1}{60}$ Hz (see <u>Table 51</u>).

When the watchdog timer function is enabled, the 8-bit timer in register Watchdg_tim_val determines the watchdog timer period (see <u>Table 51</u>).

The watchdog timer counts down from the software programmed 8-bit binary value n in register Watchdg_tim_val. When the counter reaches 1, the watchdog timer flag WDTF (register Control_2) is set logic 1 and an interrupt is generated.

The counter does not automatically reload.

When WD_CD is logic 0 (watchdog timer disabled) and the Microcontroller Unit (MCU) loads a watchdog timer value n:

- the flag WDTF is reset
- INT is cleared
- · the watchdog timer starts again

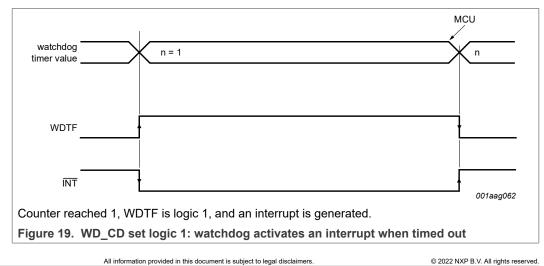
Loading the counter with 0 will:

- reset the flag WDTF
- clear INT
- stop the watchdog timer

Remark: WDTF is read only and cannot be cleared by command. WDTF can be cleared by:

- loading a value in register Watchdg_tim_val
- reading of the register Control_2

Writing a logic 0 or logic 1 to WDTF has no effect.



- When the watchdog timer counter reaches 1, the watchdog timer flag WDTF is set logic 1
- When a minute or second interrupt occurs, the minute/second flag MSF is set logic 1 (see <u>Section 7.12.1</u>).

7.10.4 Pre-defined timers: second and minute interrupt

PCF2129 has two pre-defined timers which are used to generate an interrupt either once per second or once per minute (see <u>Section 7.12.1</u>). The pulse generator for the minute or second interrupt operates from an internal 64 Hz clock. It is independent of the watchdog timer. Each of these timers can be enabled by the bits SI (second interrupt) and MI (minute interrupt) in register Control_1.

7.10.5 Clearing flags

The flags MSF, AF, and TSFx can be cleared by command. To prevent one flag being overwritten while clearing another, a logic AND is performed during the write access. A flag is cleared by writing logic 0 while a flag is not cleared by writing logic 1. Writing logic 1 results in the flag value remaining unchanged.

Two examples are given for clearing the flags. Clearing a flag is made by a write command:

- Bits labeled with must be written with their previous values
- Bits labeled with T have to be written with logic 0
- WDTF is read only and has to be written with logic 0

Repeatedly rewriting these bits has no influence on the functional behavior.

Table 52. Flag location in register Control_2

Register Bit								
	7	6	5	4	3	2	1	0
Control_2	MSF	WDTF	TSF2	AF	Т	-	-	Т

Table 53. Example values in register Control_2

Register	Bit							
	7	6	5	4	3	2	1	0
Control_2	1	0	1	1	0	0	0	0

The following tables show what instruction must be sent to clear the appropriate flag.

Table 54. Example to clear only AF (bit 4)

Register	Bit	Bit							
	7	6	5	4	3	2	1	0	
Control_2	1	0	1	0	0	0 ^[1]	0 ^[1]	0	

[1] The bits labeled as - have to be rewritten with the previous values.

Table 55. Example to clear only MSF (bit 7)

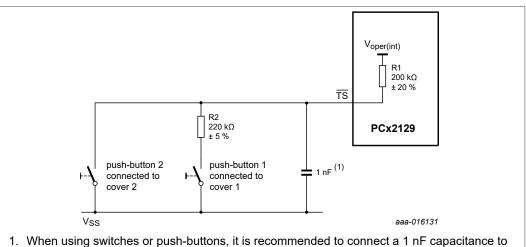
Register	Bit							
	7	6	5	4	3	2	1	0
Control_2	0	0	1	1	0	0 ^[1]	0 ^[1]	0

[1] The bits labeled as - have to be rewritten with the previous values.

7.11 Timestamp function

The PCF2129 has an active LOW timestamp input pin \overline{TS} , internally pulled with an onchip pull-up resistor to V_{oper(int)}. It also has a timestamp detection circuit which can detect two different events:

- 1. Input on pin \overline{TS} is driven to an intermediate level between power supply and ground.
- 2. Input on pin \overline{TS} is driven to ground.



 When using switches or push-buttons, it is recommended to connect a 1 nF capacitance to the TS pin to ensure proper switching.

The timestamp function is enabled by default after power-on and it can be switched off by setting the control bit TSOFF (register Timestp_ctl).

A most common application of the timestamp function is described in [1].

See <u>Section 7.12.5</u> for a description of interrupt generation from the timestamp function.

7.11.1 Timestamp flag

- When the TS input pin is driven to an intermediate level between the power supply and ground, either on the falling edge from V_{DD} or on the rising edge from ground, then the following sequence occurs:
- 2. The actual date and time are stored in the timestamp registers.
- 3. The timestamp flag TSF1 (register Control_1) is set.
- 4. If the TSIE bit (register Control_2) is active, an interrupt on the INT pin is generated.

The TSF1 flag can be cleared by command. Clearing the flag clears the interrupt. Once TSF1 is cleared, it will only be set again when a new negative or positive edge on pin \overline{TS} is detected.

Figure 20. Timestamp detection with two push-buttons on the TS pin (for example, for tamper detection)

- 1. When the \overline{TS} input pin is driven to ground, the following sequence occurs:
- 2. The actual date and time are stored in the timestamp registers.
- 3. In addition to the TSF1 flag, the TSF2 flag (register Control_2) is set.
- 4. If the TSIE bit is active, an interrupt on the INT pin is generated.

The TSF1 and TSF2 flags can be cleared by command; clearing both flags clears the interrupt. Once TSF2 is cleared, it will only be set again when \overline{TS} pin is driven to ground once again.

7.11.2 Timestamp mode

The timestamp function has two different modes selected by the control bit TSM (timestamp mode) in register Timestp_ctl:

- If TSM is logic 0 (default): in subsequent trigger events without clearing the timestamp flags, the last timestamp event is stored
- If TSM is logic 1: in subsequent trigger events without clearing the timestamp flags, the first timestamp event is stored

The timestamp function also depends on the control bit BTSE in register Control_3, see <u>Section 7.11.4</u>.

7.11.3 Timestamp registers

7.11.3.1 Register Timestp_ctl

 Table 56. Timestp_ctl - timestamp control register (address 12h) bit allocation

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Symbol	TSM	TSOFF	-	1_O_16_TIMESTP[4:0]				
Reset value	0	0	-	Х	Х	Х	Х	Х

Table 57. Timestp_ctl - timestamp control register (address 12h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Description
7	TSM	0	in subsequent events without clearing the timestamp flags, the last event is stored
		1	in subsequent events without clearing the timestamp flags, the first event is stored
6	TSOFF	0	timestamp function active
		1	timestamp function disabled
5	-	-	unused
4 to 0	1_O_16_TIMESTP[4:0]		$\frac{1}{16}$ second timestamp information coded in BCD format

7.11.3.2 Register Sec_timestp

 Table 58. Sec_timestp - second timestamp register (address 13h) bit allocation

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0	
Symbol	-		SECOND_TIMESTP (0 to 59)						
Reset value	-	Х	Х	Х	Х	Х	Х	Х	

Table 59. Sec_timestp - second timestamp register (address 13h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	-	-	-	unused
6 to 4	SECOND_TIMESTP	0 to 5	ten's place	second timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

7.11.3.3 Register Min_timestp

Table 60. Min_timestp - minute timestamp register (address 14h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0		
Symbol	-		MINUTE_TIMESTP (0 to 59)							
Reset value	-	Х	Х	Х	Х	Х	Х	Х		

Table 61. Min_timestp - minute timestamp register (address 14h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7	-	-	-	unused
6 to 4	MINUTE_TIMESTP	0 to 5	ten's place	minute timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

7.11.3.4 Register Hour_timestp

Table 62. Hour_timestp - hour timestamp register (address 15h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0	
Symbol	-	-	AMPM HOUR_TIMESTP (1 to 12) in 12-hour mode						
				HOUR_TIMESTP (0 to 23) in 24-hour mode					
PCE2129			All information provided in this document is subject to legal disclaimers						

 Table 62. Hour_timestp - hour timestamp register (address 15h) bit allocation...continued

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0
Reset value	-	-	Х	Х	Х	Х	Х	Х

Table 63. Hour_timestp - hour timestamp register (address 15h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 6	-	-	-	unused
12-hour mod	le ^[1]			
5	АМРМ	0	-	indicates AM
		1	-	indicates PM
4	HOUR_TIMESTP	0 to 1	ten's place	hour timestamp information coded in BCD format
3 to 0		0 to 9	unit place	when in 12-hour mode
24-hour mod	le ^[1]			
5 to 4	HOUR_TIMESTP	0 to 2	ten's place	hour timestamp information coded in BCD format
3 to 0		0 to 9	unit place	when in 24-hour mode

[1] Hour mode is set by the bit 12_24 in register Control_1.

7.11.3.5 Register Day_timestp

Table 64. Day_timestp - day timestamp register (address 16h) bit allocation

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0		
Symbol	-	-		DAY_TIMESTP (1 to 31)						
Reset value	-	-	Х	Х	Х	Х	Х	Х		

Table 65. Day_timestp - day timestamp register (address 16h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 6	-	-	-	unused
5 to 4	DAY_TIMESTP	0 to 3	ten's place	day timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

7.11.3.6 Register Mon_timestp

 Table 66. Mon_timestp - month timestamp register (address 17h) bit allocation

 Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0	
Symbol	-	-	-	MONTH_TIMESTP (1 to 12)					
Reset value	-	-	-	Х	Х	Х	Х	Х	

Table 67. Mon_timestp - month timestamp register (address 17h) bit description

Bit positions labeled as - are not implemented and return 0 when read. Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 5	-	-	-	unused
4	MONTH_TIMESTP	0 to 1	ten's place	month timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

7.11.3.7 Register Year_timestp

Table 68. Year_timestp - year timestamp register (address 18h) bit allocation

Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	7	6	5	4	3	2	1	0		
Symbol		YEAR_TIMESTP (0 to 99)								
Reset value	Х	Х	Х	Х	Х	Х	Х	X		

Table 69. Year_timestp - year timestamp register (address 18h) bit description Bits labeled as X are undefined at power-on and unchanged by subsequent resets.

Bit	Symbol	Value	Place value	Description
7 to 4	YEAR_TIMESTP	0 to 9	ten's place	year timestamp information coded in BCD format
3 to 0		0 to 9	unit place	

7.11.4 Dependency between Battery switch-over and timestamp

The timestamp function depends on the control bit BTSE in register Control-_3:

BTSE	BF		Description
0	-	[1]	the battery switch-over does not affect the timestamp registers
1			If a battery switch-over event occurs:

BTSE	BF		Description	
	0	[1]	the timestamp registers store the time and date when the switch-over occurs; after this event occurred BF is set logic 1	
	1		the timestamp registers are not modified; in this condition subsequent battery switch- over events or falling edges on pin TS are not registered	

 Table 70. Battery switch-over and timestamp...continued

[1] Default value.

7.12 Interrupt output, INT

PCF2129 has an interrupt output pin INT which is open-drain, active LOW (requiring a pull-up resistor if used). Interrupts may be sourced from different places:

- · second or minute timer
- watchdog timer
- alarm
- timestamp
- · battery switch-over
- · battery low detection

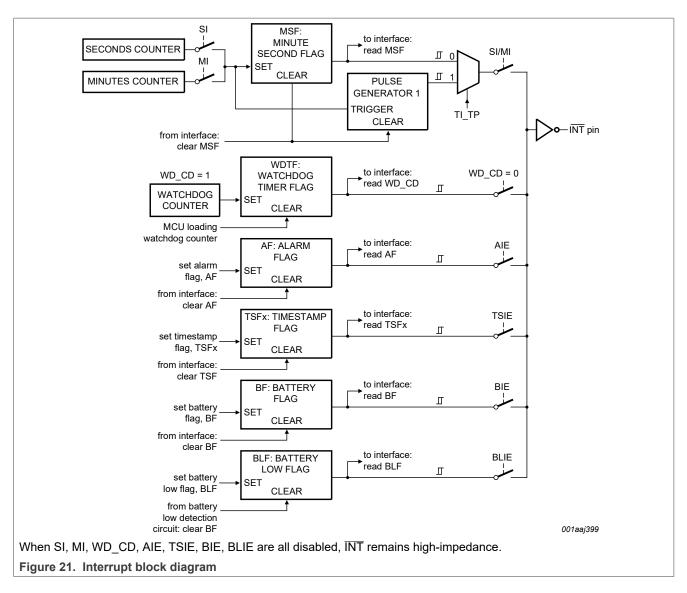
The control bit TI_TP (register Watchdg_tim_ctl) is used to configure whether the interrupts generated from the second/minute timer (flag MSF in register Control_2) are pulsed signals or a permanently active signal. All the other interrupt sources generate a permanently active interrupt signal which follows the status of the corresponding flags. When the interrupt sources are all disabled, INT remains high-impedance.

- The flags MSF, AF, TSFx, and BF can be cleared by command.
- The flag WDTF is read only. How it can be cleared is explained in Section 7.10.5.
- The flag BLF is read only. It is cleared automatically from the battery low detection circuit when the battery is replaced.

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7.12.1 Minute and second interrupts

Minute and second interrupts are generated by predefined timers. The timers can be enabled independently from one another by the bits MI and SI in register Control_1. However, a minute interrupt enabled on top of a second interrupt cannot be distinguishable since it occurs at the same time.

The minute/second flag MSF (register Control_2) is set logic 1 when either the seconds or the minutes counter increments according to the enabled interrupt (see <u>Table 71</u>). The MSF flag can be cleared by command.

[МІ	SI	Result on INT	Result on MSF
	0	0	no interrupt generated	MSF never set
	1	0	1 1	MSF set when minutes counter increments

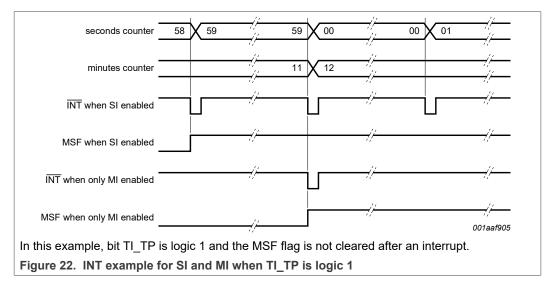
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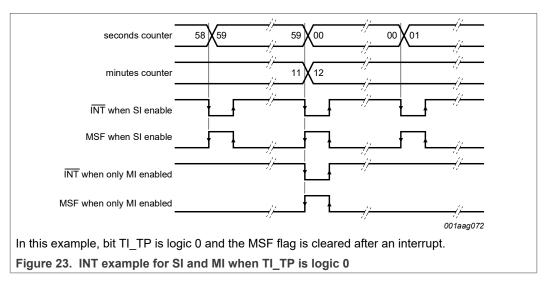
МІ	SI	Result on INT	Result on MSF
0	1	an interrupt once per se	econd MSF set when seconds counter increments
1	1	an interrupt once per se	econd MSF set when seconds counter increments

Table 71. Effect of bits MI and SI on pin INT and bit MSF...continued

When MSF is set logic 1:

- If TI_TP is logic 1, the interrupt is generated as a pulsed signal.
- If TI_TP is logic 0, the interrupt is permanently active signal that remains until MSF is cleared.

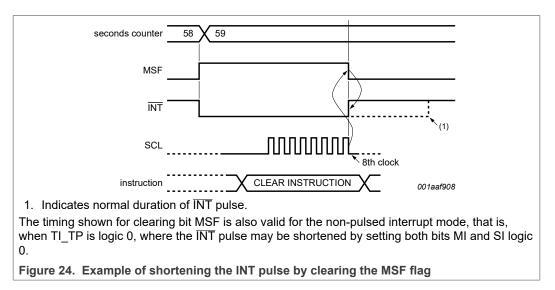




The pulse generator for the minute/second interrupt operates from an internal 64 Hz clock and generates a pulse of $\frac{1}{64}$ seconds in duration.

7.12.2 INT pulse shortening

If the MSF flag (register Control_2) is cleared before the end of the $\overline{\text{INT}}$ pulse, then the $\overline{\text{INT}}$ pulse is shortened. This allows the source of a system interrupt to be cleared immediately when it is serviced, that is, the system does not have to wait for the completion of the pulse before continuing; see <u>Figure 24</u>. Instructions for clearing the bit MSF can be found in <u>Section 7.10.5</u>.



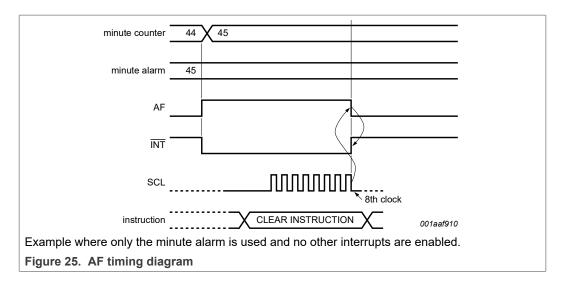
7.12.3 Watchdog timer interrupts

The generation of interrupts from the watchdog timer is controlled using the WD_CD bit (register Watchdg_tim_ctl). The interrupt is generated as an active signal which follows the status of the watchdog timer flag WDTF (register Control_2). No pulse generation is possible for watchdog timer interrupts.

The interrupt is cleared when the flag WDTF is reset. WDTF is a read-only bit and cannot be cleared by command. Instructions for clearing it can be found in <u>Section 7.10.5</u>.

7.12.4 Alarm interrupts

Generation of interrupts from the alarm function is controlled by the bit AIE (register Control_2). If AIE is enabled, the INT pin follows the status of bit AF (register Control_2). Clearing AF immediately clears INT. No pulse generation is possible for alarm interrupts.



7.12.5 Timestamp interrupts

Interrupt generation from the timestamp function is controlled using the TSIE bit (register Control_2). If TSIE is enabled, the \overline{INT} pin follows the status of the flags TSFx. Clearing the flags TSFx immediately clears \overline{INT} . No pulse generation is possible for timestamp interrupts.

7.12.6 Battery switch-over interrupts

Generation of interrupts from the battery switch-over is controlled by the BIE bit (register Control_3). If BIE is enabled, the INT pin follows the status of bit BF in register Control_3 (see <u>Table 70</u>). Clearing BF immediately clears INT. No pulse generation is possible for battery switch-over interrupts.

7.12.7 Battery low detection interrupts

Generation of interrupts from the battery low detection is controlled by the BLIE bit (register Control_3). If BLIE is enabled, the \overline{INT} pin follows the status of bit BLF (register Control_3). The interrupt is cleared when the battery is replaced (BLF is logic 0) or when bit BLIE is disabled (BLIE is logic 0). BLF is read only and therefore cannot be cleared by command.

7.13 External clock test mode

A test mode is available which allows on-board testing. In this mode, it is possible to set up test conditions and control the operation of the RTC.

The test mode is entered by setting bit EXT_TEST logic 1 (register Control_1). Then pin CLKOUT becomes an input. The test mode replaces the internal clock signal (64 Hz) with the signal applied to pin CLKOUT. Every 64 positive edges applied to pin CLKOUT generate an increment of one second.

The signal applied to pin CLKOUT should have a minimum pulse width of 300 ns and a maximum period of 1 000 ns. The internal clock, now sourced from CLKOUT, is divided down by a 2^6 divider chain called prescaler (see <u>Table 72</u>). The prescaler can be set into a known state by using bit STOP. When bit STOP is logic 1, the prescaler is reset to 0. STOP must be cleared before the prescaler can operate again.

From a stop condition, the first 1 second increment will take place after 32 positive edges on pin CLKOUT. Thereafter, every 64 positive edges cause a 1 second increment.

Remark: Entry into test mode is not synchronized to the internal 64 Hz clock. When entering the test mode, no assumption as to the state of the prescaler can be made.

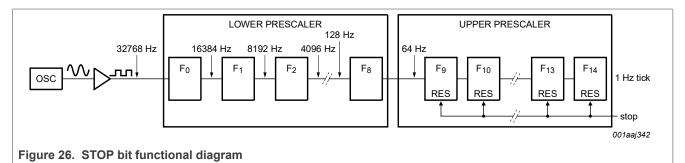
Operating example:

- 1. Set EXT_TEST test mode (register Control_1, EXT_TEST is logic 1).
- 2. Set bit STOP (register Control_1, STOP is logic 1).
- 3. Set time registers to desired value.
- 4. Clear STOP (register Control_1, STOP is logic 0).
- 5. Apply 32 clock pulses to CLKOUT.
- 6. Read time registers to see the first change.
- 7. Apply 64 clock pulses to CLKOUT.
- 8. Read time registers to see the second change.

Repeat 7 and 8 for additional increments.

7.14 STOP bit function

The function of the STOP bit is to allow for accurate starting of the time circuits. STOP causes the upper part of the prescaler (F_9 to F_{14}) to be held in reset and thus no 1 Hz ticks are generated. The time circuits can then be set and will not increment until the STOP bit is released. STOP doesn't affect the CLKOUT signal but the output of the prescaler in the range of 32 Hz to 1 Hz (see Figure 26).



The lower stages of the prescaler, F_0 to F_8 , are not reset and because the I^2 C-bus and the SPI-bus are asynchronous to the crystal oscillator, the accuracy of restarting the time circuits is between 0 and one 64 Hz cycle (0.484 375 s and 0.500 000 s), see <u>Table 72</u> and Figure 27.

 Table 72. First increment of time circuits after stop release

Bit STOP	Prescaler bits ^[1] F_0 to F_8 - F_9 to F_{14}	1 Hz tick	Time hh:mm:ss	Comment		
Clock is I	Clock is running normally					
0	010000111-010100 12:45:12 prescaler counting normally					
STOP bit	is activated by user. F ₀	to F ₈ are not i	reset and valu	es cannot be predicted externally		
1	xxxxxxx-000000		12:45:12	prescaler is reset; time circuits are frozen		
New time	New time is set by user					
1	xxxxxxx-000000		08:00:00	prescaler is reset; time circuits are frozen		

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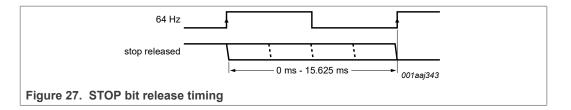
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Bit	Prescaler bits ^[1]	1 Hz tick	Time	Comment
STOP	F_0 to F_8 - F_9 to F_{14}		hh:mm:ss	
STOP bit	is released by user			
0	xxxxxxx-000000	0 8	08:00:00	prescaler is now running
0	xxxxxxx-100000	0.50000	08:00:00	
0	xxxxxxx-100000		08:00:00	
0	xxxxxxx-110000	0.48437	08:00:00	
:	:		:	
0	111111111-111110		08:00:00	
0	00000000-000001		08:00:01	0 to 1 transition of F_{14} increments the time circuits
0	10000000-000001		08:00:01	
:	:	~	:	
0	111111111-111111		08:00:01	
0	00000000-000000		08:00:01	
0	10000000-000000			
:	:] `	:	
0	111111111-111110	001aaj479	08:00:01	
0	00000000-000001]	08:00:02	0 to 1 transition of F_{14} increments the time circuits

 Table 72. First increment of time circuits after stop release...continued

[1] F_0 is clocked at 32.768 kHz.

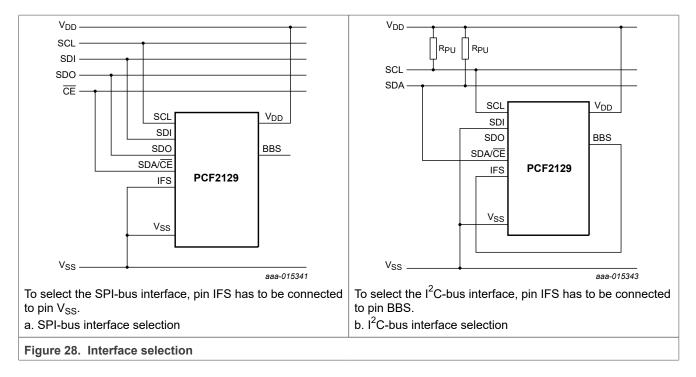


8 Interfaces

The PCF2129 has an I^2 C-bus or SPI-bus interface using the same pins. The selection is done using the interface selection pin IFS (see <u>Table 73</u>).

 Table 73. Interface selection input pin IFS

Pin	Connection	Bus interface	Reference	
IFS	V _{SS}	SPI-bus	Section 8.1	
	BBS	l ² C-bus	Section 8.2	



Accurate RTC with integrated quartz crystal for industrial applications

8.1 SPI-bus interface

Data transfer to and from the device is made by a 3 line SPI-bus (see <u>Table 74</u>). The data lines for input and output are split. The data input and output line can be connected together to facilitate a bidirectional data bus (see <u>Figure 29</u>). The SPI-bus is initialized whenever the chip enable line pin SDA/CE is inactive.

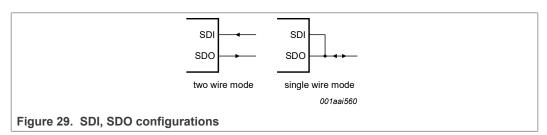


Table	74.	Serial	interface

Symbol	Function		Description
SDA/CE	chip enable input; active LOW	[1]	when HIGH, the interface is reset; input may be higher than V _{DD}
SCL	serial clock input		when SDA/CE is HIGH, input may float; input may be higher than V _{DD}
SDI	serial data input		when SDA/CE is HIGH, input may float; input may be higher than V _{DD} ; input data is sampled on the rising edge of SCL

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 Table 74. Serial interface...continued

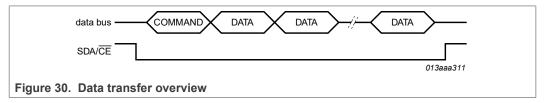
Symbol	Function	C	Description			
SDO	serial data output	q	bush-pull output; drives from V _{SS} to V _{oper(int)} (V _{BBS}); output data is changed on the falling edge of SCL			

[1] The chip enable must not be wired permanently LOW.

8.1.1 Data transmission

The chip enable signal is used to identify the transmitted data. Each data transfer is a whole byte, with the Most Significant Bit (MSB) sent first.

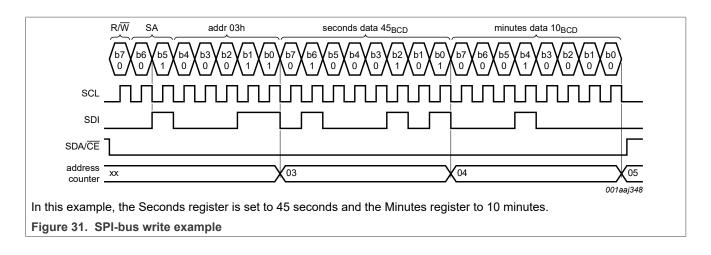
The transmission is controlled by the active LOW chip enable signal SDA/CE. The first byte transmitted is the command byte. Subsequent bytes are either data to be written or data to be read (see Figure 30).

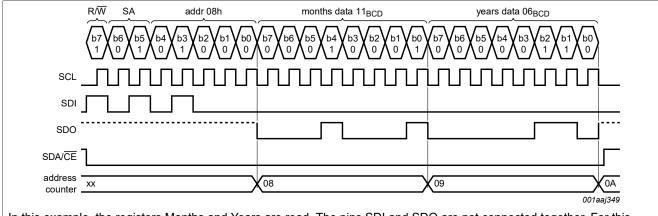


The command byte defines the address of the first register to be accessed and the read/ write mode. The address counter will auto increment after every access and will reset to zero after the last valid register is accessed. The R/W bit defines if the following bytes are read or write information.

Bit	Symbol	Value	Description
7	R/W		data read or write selection
		0	write data
		1	read data
6 to 5	SA	01	subaddress; other codes will cause the device to ignore data transfer
4 to 0	RA	00h to 1Bh	register address

Table 75. Command byte definition





In this example, the registers Months and Years are read. The pins SDI and SDO are not connected together. For this configuration, it is important that pin SDI is never left floating. It must always be driven either HIGH or LOW. If pin SDI is left open, high I_{DD} currents may result.

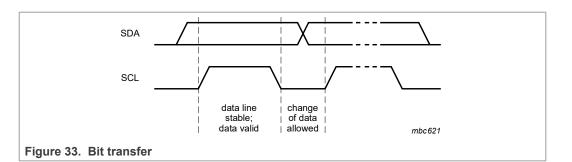
Figure 32. SPI-bus read example

8.2 I²C-bus interface

The I²C-bus is for bidirectional, two-line communication between different ICs or modules. The two lines are a Serial DAta line (SDA) and a Serial CLock line (SCL). Both lines are connected to a positive supply by a pull-up resistor. Data transfer is initiated only when the bus is not busy.

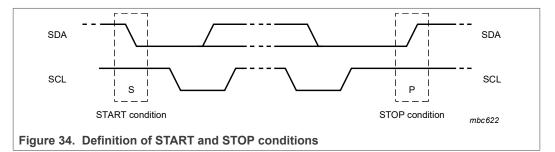
8.2.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line remains stable during the HIGH period of the clock pulse as changes in the data line at this time are interpreted as control signals (see Figure 33).



8.2.2 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line, while the clock is HIGH, is defined as the START condition S. A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition P (see Figure 34).

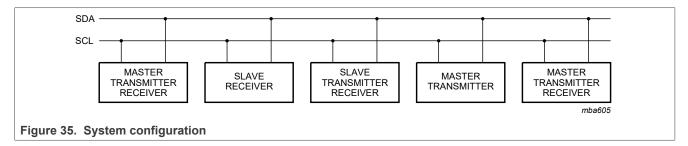


Remark: For the PCF2129, a repeated START is not allowed. Therefore a STOP has to be released before the next START.

8.2.3 System configuration

A device generating a message is a transmitter; a device receiving a message is the receiver. The device that controls the message is the master; and the devices which are controlled by the master are the slaves.

The PCF2129 can act as a slave transmitter and a slave receiver.

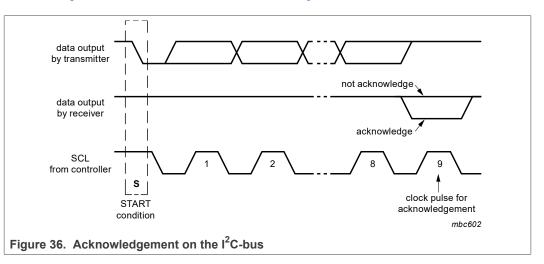


8.2.4 Acknowledge

The number of data bytes transferred between the START and STOP conditions from transmitter to receiver is unlimited. Each byte of 8 bits is followed by an acknowledge cycle.

- A slave receiver which is addressed must generate an acknowledge after the reception of each byte.
- Also a master receiver must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter.
- The device that acknowledges must pull-down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse (set-up and hold times must be considered).
- A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event, the transmitter must leave the data line HIGH to enable the master to generate a STOP condition.

Acknowledgement on the I^2 C-bus is illustrated in <u>Figure 36</u>.



8.2.5 I²C-bus protocol

After a start condition, a valid hardware address has to be sent to a PCF2129 device. The appropriate I^2 C-bus slave address is 1010 001. The entire I^2 C-bus slave address byte is shown in <u>Table 76</u>.

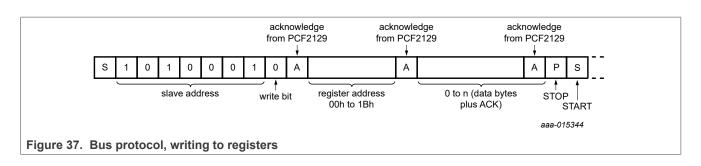
	Slave address							
Bit	7	6	5	4	3	2	1	0
	MSB							LSB
	1	0	1	0	0	0	1	R/W

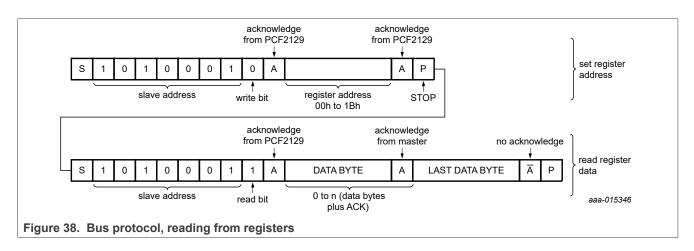
The R/W bit defines the direction of the following single or multiple byte data transfer (read is logic 1, write is logic 0).

For the format and the timing of the START condition (S), the STOP condition (P), and the acknowledge (A) refer to the I^2 C-bus specification [7] and the characteristics table (<u>Table 81</u>). In the write mode, a data transfer is terminated by sending a STOP condition. A repeated START (Sr) condition is not applicable.

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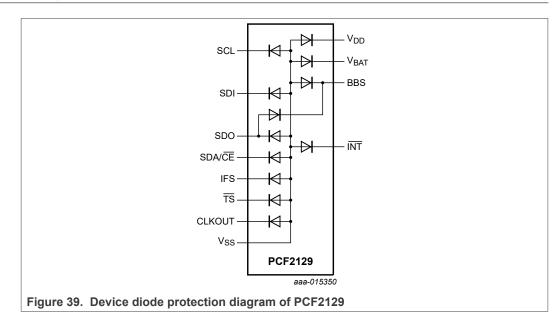


8.3 Bus communication and battery backup operation

To save power during battery backup operation (see <u>Section 7.5.1</u>), the bus interfaces are inactive. Therefore the communication via I^2C - or SPI-bus should be terminated before the supply of the PCF2129 is switched from V_{DD} to V_{BAT}.

Remark: If the I^2C -bus communication was terminated uncontrolled, the I^2C -bus has to be reinitialized by sending a STOP followed by a START after the device switched back from battery backup operation to V_{DD} supply operation.

9 Internal circuitry



10 Safety notes



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices. Such precautions are described in the *ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A* or equivalent standards.

11 Limiting values

Table 77. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DD}	supply voltage			-0.5	+6.5	V
I _{DD}	supply current			-50	+50	mA
Vi	input voltage			-0.5	+6.5	V
l _l	input current			-10	+10	mA
Vo	output voltage			-0.5	+6.5	V
I _O	output current			-10	+10	mA
		at pin SDA/CE		-10	+20	mA
V _{BAT}	battery supply voltage			-0.5	+6.5	V
P _{tot}	total power dissipation			-	300	mW
V _{ESD}	electrostatic discharge	НВМ	[1]	-	±4 000	V
	voltage	CDM	[2]	-	±1 250	V

Table 77. Limiting values...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
l _{lu}	latch-up current		[3]	-	200	mA
T _{stg}	storage temperature		[4]	-55	+85	°C
T _{amb}	ambient temperature	operating device		-40	+85	°C

Pass level; Human Body Model (HBM) according to [2]. Pass level; Charged-Device Model (CDM), according to [3].

[1] [2] [3]

Pass level; latch-up testing according to [4] at maximum ambient temperature $(T_{amb(max)})$. According to the store and transport requirements (see [8]) the devices have to be stored at a temperature of +8 °C to +45 °C and a humidity of 25 % to [4] 75 %.

12 Static characteristics

Table 78. Static characteristics

 V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = -40 °C to +85 °C, unless otherwise specified.

Symbol P	arameter	Conditions		Min	Тур	Max	Unit	
Supplies						I		
V _{DD} su	upply voltage		[1]	1.8	-	4.2	V	
V _{BAT} ba	attery supply voltage			1.8	-	4.2	V	
V _{DD(cal)} ca	alibration supply voltage			-	3.3	-	V	
V _{low} lo	w voltage			-	1.2	-	V	
I _{DD} supply current		interface active; supplied by V _{DD}		1	L			
		SPI-bus (f _{SCL} = 6.5 MHz)		-	-	800	μA	
		l ² C-bus (f _{SCL} = 400 kHz)		-	-	200	μA	
	interface inactive $(f_{SCL} = 0 \text{ Hz})^{[2]}$; TCR[1:0] = 00 (see <u>Table 12</u>)							
		PWRMNG[2:0] = 111 (see <u>Table 18</u>); TSOFF = 1 (see <u>Table 57</u>); COF[2:0] = 111 (see <u>Table 14</u>)						
		V _{DD} = 1.8 V		-	470	-	nA	
		V _{DD} = 3.3 V		-	700	1 500	nA	
		V _{DD} = 4.2 V		-	800	-	nA	
		PWRMNG[2:0] = 111 (see <u>Table 18</u>); TSOFF = 1 (see <u>Table 57</u>); COF[2:0] = 000 (see <u>Table 14</u>)						
		V _{DD} = 1.8 V		-	560	-	nA	
		V _{DD} = 3.3 V		-	850	-	nA	
		V _{DD} = 4.2 V		-	1 050	-	nA	
		PWRMNG[2:0] = 000 (see TSOFF = 0 (see <u>Table 57</u>); COF[2:0] = 111 (see <u>Table</u>		<u>18</u>);	1	1	I	
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Table 78. Static characteristics...continued

Symbol	Parameter	Conditions		Min	Тур	Мах	Unit			
		V _{DD} or V _{BAT} = 1.8 V	[3]	-	1 750	-	nA			
		V _{DD} or V _{BAT} = 3.3 V	[3]	-	2 150	-	nA			
		V _{DD} or V _{BAT} = 4.2 V	[3]	-	2 350	3 500	nA			
		PWRMNG[2:0] = 000 (see <u>Table 18</u>); TSOFF = 0 (see <u>Table 57</u>); COF[2:0] = 000 (see <u>Table 14</u>)								
		V_{DD} or V_{BAT} = 1.8 V	[3]		1 840	-	nA			
		V _{DD} or V _{BAT} = 3.3 V	[3]	-	2 300	-	nA			
		V _{DD} or V _{BAT} = 4.2 V	[3]	-	2 600	-	nA			
I _{L(bat)}	battery leakage current	V _{DD} is active supply; V _{BAT} = 3.0 V		-	50	100	nA			
Power ma	nagement		1	1						
V _{th(sw)bat}	battery switch threshold voltage			-	2.5	-	V			
V _{th(bat)low}	low battery threshold			-	2.5	-	V			
	voltage	T _{amb} = 25 °C		2.25	-	2.85	V			
Inputs ^[4]						I				
VI	input voltage			-0.5	-	V _{DD} + 0.5	V			
VIL	LOW-level input voltage			-	-	0.25V _{DD}	V			
		T _{amb} = -20 °C to +85 °C; V _{DD} > 2.0 V		-	-	0.3V _{DD}	V			
V _{IH}	HIGH-level input voltage			0.7V _{DD}	-	-	V			
ILI	input leakage current	$V_{I} = V_{DD} \text{ or } V_{SS}$		-	0	-	μA			
		post ESD event		-1	-	+1	μA			
C _i	input capacitance		[5]	-	-	7	pF			
Outputs										
V _O	output voltage	on pins CLKOUT, INT, referring to external pull-up		-0.5	-	+5.5	V			
		on pin BBS		1.8	-	4.2	V			
		on pin SDO		-0.5	-	V _{DD} + 0.5	V			
V _{OH}	HIGH output voltage	on pin SDO		0.8V _{DD}	-	V _{DD}	V			
V _{OL}	LOW output voltage	on pins CLKOUT, INT, and SDO		V _{SS}	-	0.2V _{DD}	V			
I _{OL}	LOW-level output current	output sink current; V _{OL} = 0.4 V	1							
		on pin SDA/CE	[6]	3	17	-	mA			
		on all other outputs		1.0	-	-	mA			

Table 78. Static characteristics...continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _{ОН}	HIGH-level output current	output source current; on pin SDO; $V_{OH} = 3.8 V;$ $V_{DD} = 4.2 V$	1.0	-	-	mA
I _{LO}	output leakage current	$V_{O} = V_{DD}$ or V_{SS}	-	0	-	μA
		post ESD event	-1	-	+1	μA

[1]

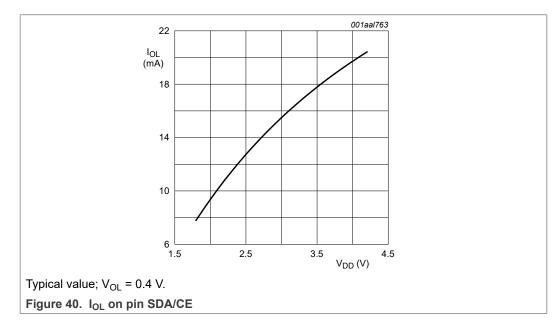
For reliable oscillator start-up at power-on: $V_{DD(po)min} = V_{DD(min)} + 0.3 V$. Timer source clock = $\frac{1}{60}$ Hz, level of pins SDA/CE, SDI, and SCL is V_{DD} or V_{SS} . When the device is supplied by the V_{BAT} pin instead of the V_{DD} pin, the current values for I_{BAT} are as specified for I_{DD} under the same conditions. The I^2 C-bus and SPI-bus interfaces of PCF2129 are 5 V tolerant.

[2] [3] [4]

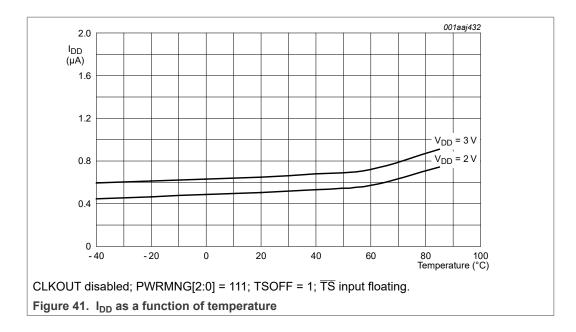
[5] Tested on sample basis.

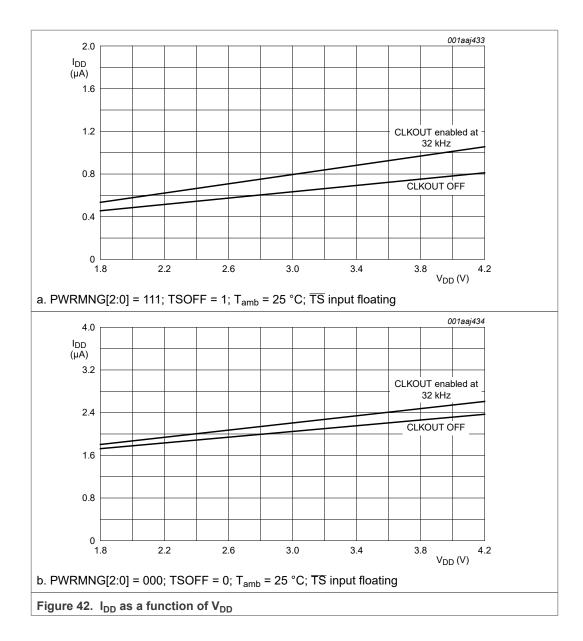
For further information, see Figure 40. [6]

12.1 Current consumption characteristics, typical

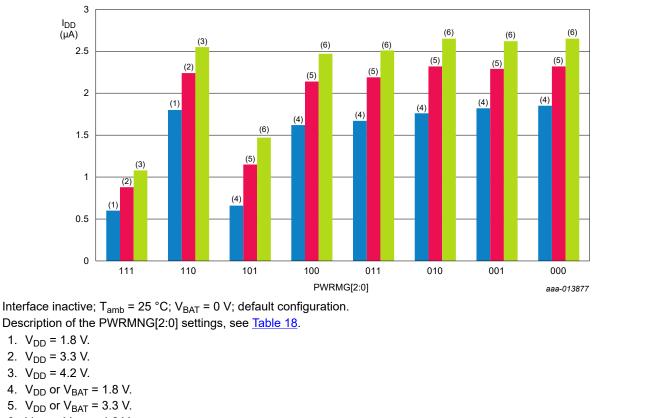


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6. V_{DD} or $V_{BAT} = 4.2$ V.

Figure 43. Typical I_{DD} as a function of the power management settings

12.2 Frequency characteristics

Table 79.	Frequency	characteristics
-----------	-----------	-----------------

 V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = +25 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
f _o	output frequency	on pin CLKOUT; V _{DD} or V _{BAT} = 3.3 V; COF[2:0] = 000; AO[3:0] = 1000		-	32.768	-	kHz
∆f/f	frequency stability	V_{DD} or V_{BAT} = 3.3 V					
		PCF2129AT					
		T _{amb} = -15 °C to +60 °C	[1][2]	-	±3	±5	ppm
		T_{amb} = -25 °C to -15 °C and T_{amb} = +60 °C to +65 °C	[1][2]	-	±5	±10	ppm
		PCF2129T			I	1	
		T _{amb} = -30 °C to +80 °C	[1][2]	-	±3	±8	ppm
		T_{amb} = -40 °C to -30 °C and T_{amb} = +80 °C to +85 °C	[1][2]	-	±5	±15	ppm
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Table 79. Frequency characteristics...continued

 V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = +25 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$\Delta f_{xtal}/f_{xtal}$	relative crystal	crystal aging					
	frequency variation	PCF2129AT					
		first year; V _{DD} or V _{BAT} = 3.3 V	[3]	-	-	±3	ppm
		PCF2129T				I	
		first year	[3]	-	-	±3	ppm
		ten years		-	-	±8	ppm
Δf/ΔV	frequency variation with voltage	on pin CLKOUT		-	±1	-	ppm/V

 \pm 1 ppm corresponds to a time deviation of \pm 0.0864 seconds per day. Only valid if CLKOUT frequencies are not equal to 32.768 kHz or if CLKOUT is disabled. Not production tested. Effects of reflow soldering are included (see [1]). [1] [2] [3]

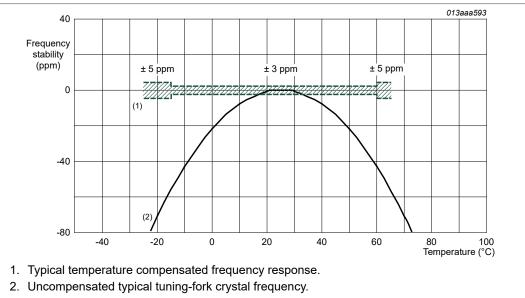
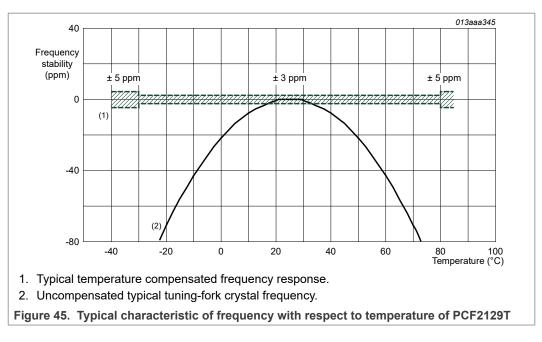


Figure 44. Typical characteristic of frequency with respect to temperature of PCF2129AT



13 Dynamic characteristics

13.1 SPI-bus timing characteristics

Table 80. SPI-bus characteristics

 V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = -40 °C to +85 °C, unless otherwise specified. All timing values are valid within the operating supply voltage at ambient temperature and referenced to V_{IL} and V_{IH} with an input voltage swing of V_{SS} to V_{DD} (see <u>Figure 46</u>).

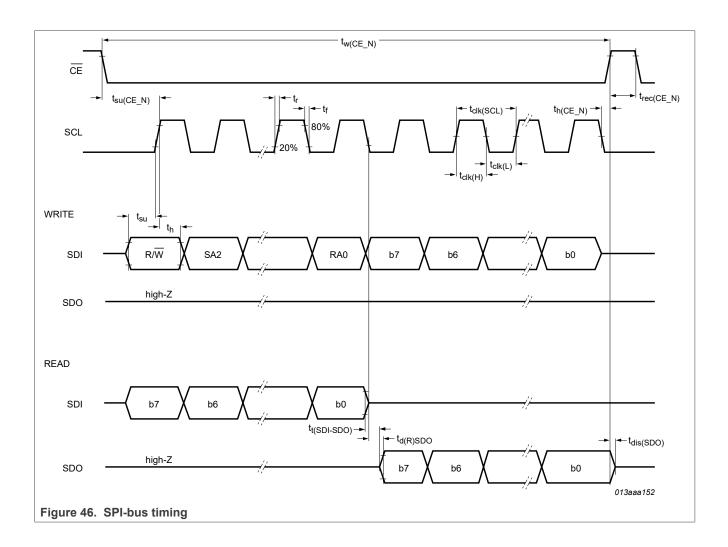
Symbol	Parameter	Conditions	V _{DD} =	1.8 V	V _{DD} = 4.2 V		Unit
			Min	Max	Min	Мах	
Pin SCL							
f _{clk(SCL)}	SCL clock frequency		-	2.0	-	6.5	MHz
t _{SCL}	SCL time		800	-	140	-	ns
t _{clk(H)}	clock HIGH time		100	-	70	-	ns
t _{clk(L)}	clock LOW time		400	-	70	-	ns
t _r	rise time	for SCL signal	-	100	-	100	ns
t _f	fall time	for SCL signal	-	100	-	100	ns
Pin SDA/	E				I	I	
t _{su(CE_N)}	CE_N set-up time		60	-	30	-	ns
t _{h(CE_N)}	CE_N hold time		40	-	25	-	ns
t _{rec(CE_N)}	CE_N recovery time		100	-	30	-	ns
t _{w(CE_N)}	CE_N pulse width		-	0.99	-	0.99	s
Pin SDI	•						
t _{su}	set-up time	set-up time for SDI data	70	-	20	-	ns

Table 80. SPI-bus characteristics...continued

 V_{DD} = 1.8 V to 4.2 V; V_{SS} = 0 V; T_{amb} = -40 °C to +85 °C, unless otherwise specified. All timing values are valid within the operating supply voltage at ambient temperature and referenced to V_{IL} and V_{IH} with an input voltage swing of V_{SS} to V_{DD} (see <u>Figure 46</u>).

Symbol	Parameter	Conditions		V _{DD} =	1.8 V	V _{DD} =	V _{DD} = 4.2 V	
				Min	Max	Min	Max	
t _h	hold time	hold time for SDI data		70	-	20	-	ns
Pin SDO	-				I			
t _{d(R)SDO}	SDO read delay time	C _L = 50 pF		-	225	-	55	ns
t _{dis(SDO)}	SDO disable time		[1]	-	90	-	25	ns
$t_{t(SDI-SDO)}$	transition time from SDI to SDO	to avoid bus conflict		0	-	0	-	ns

[1] No load value; bus is held up by bus capacitance; use RC time constant with application values.



13.2 I²C-bus timing characteristics

Table 81. I²C-bus characteristics

All timing characteristics are valid within the operating supply voltage and ambient temperature range and reference to 30 % and 70 % with an input voltage swing of V_{SS} to V_{DD} (see Figure 47).

Symbol	Parameter	Parameter			de Fast-mode (Unit
			Min	Мах	Min	Max	
Pin SCL			1		I		
f _{SCL}	SCL clock frequency	[1]	0	100	0	400	kHz
t _{LOW}	LOW period of the SCL clock		4.7	-	1.3	-	μs
t _{HIGH}	HIGH period of the SCL clock		4.0	-	0.6	-	μs
Pin SDA/	E			L	ŀ	, I	l
t _{SU;DAT}	data set-up time		250	-	100	-	ns
t _{HD;DAT}	data hold time		0	-	0	-	ns
Pins SCL	and SDA/CE				ł	1	
t _{BUF}	bus free time between a STOP and START condition		4.7	-	1.3	-	μs
t _{su;sто}	set-up time for STOP condition		4.0	-	0.6	-	μs
t _{HD;STA}	hold time (repeated) START condition		4.0	-	0.6	-	μs
t _{SU;STA}	set-up time for a repeated START condition		4.7	-	0.6	-	μs
t _r	rise time of both SDA and SCL signals	[2][3][4]	-	1 000	20 + 0.1C _b	300	ns
t _f	fall time of both SDA and SCL signals	[2][3][4]	-	300	20 + 0.1C _b	300	ns
t _{VD;ACK}	data valid acknowledge time	[5]	0.1	3.45	0.1	0.9	μs
t _{VD;DAT}	data valid time	[6]	300	-	75	-	ns
t _{SP}	pulse width of spikes that must be suppressed by the input filter	[7]	-	50	-	50	ns

[1] The minimum SCL clock frequency is limited by the bus time-out feature which resets the serial bus interface if either the SDA or SCL is held LOW for a minimum of 25 ms. The bus time-out feature must be disabled for DC operation.

A master device must internally provide a hold time of at least 300 ns for the SDA signal (refer to the V_{IL} of the SCL signal) in order to bridge the [2]

[3]

A master device must internally provide a noid time of at least 300 ns for the SDA signal (refer to the V_{IL} of the SCL signal) in order to bridge the undefined region of the falling edge of SCL. C_b is the total capacitance of one bus line in pF. The maximum t_f for the SDA and SCL bus lines is 300 ns. The maximum fall time for the SDA output stage, t_f is 250 ns. This allows series protection resistors to be connected between the SDA/CE pin, the SCL pin, and the SDA/SCL bus lines without exceeding the maximum t_f . $t_{VD;ACK}$ is the time of the acknowledgement signal from SCL LOW to SDA (out) LOW. $t_{VD;DAT}$ is the minimum time for valid SDA (out) data following SCL LOW. Input filters on the SDA and SCL inputs suppress noise spikes of less than 50 ns. [4]

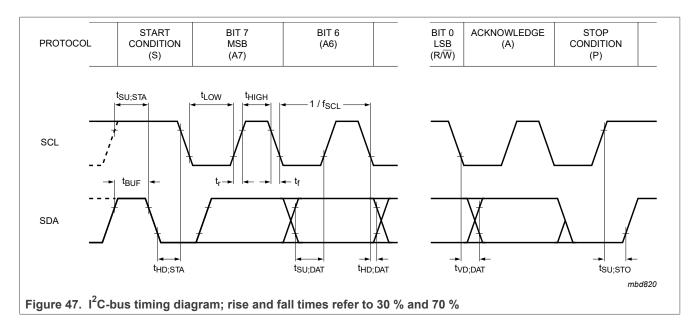
[5]

[6] [7]

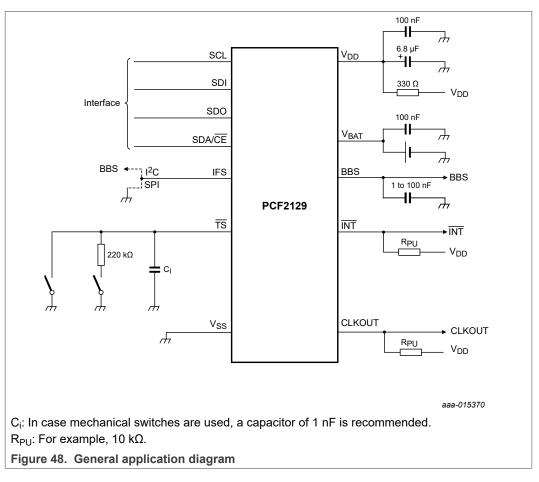
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14 Application information



For information about application configuration, see [1].

15 Test information

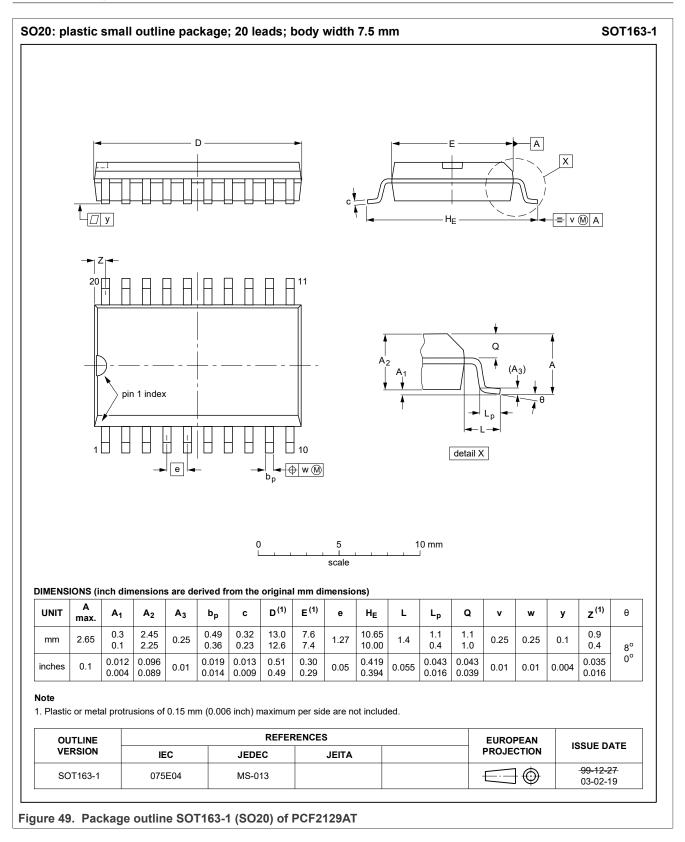
15.1 Quality information

UL Component Recognition



This (component or material) is Recognized by UL. Representative samples of this component have been evaluated by UL and meet applicable UL requirements.

16 Package outline



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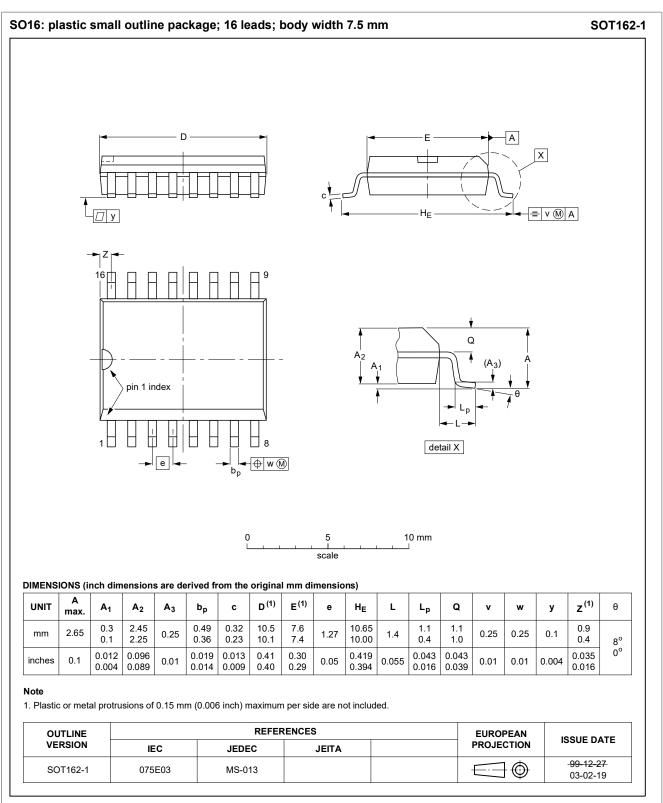


Figure 50. Package outline SOT162-1 (SO16) of PCF2129T

PCF2129 Product data sheet

17 Packing information

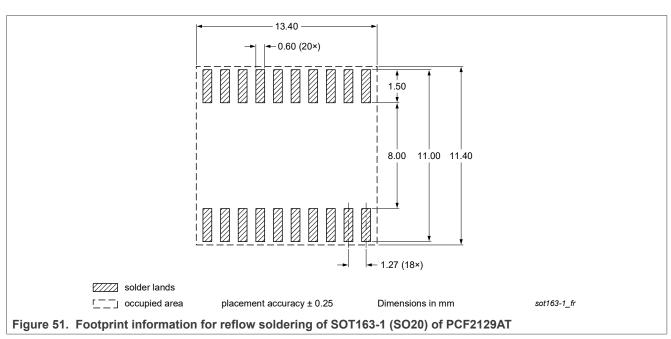
17.1 Tape and reel information

For tape and reel packing information, see

- [5] for the PCF2129T.
- [6] for the PCF2129AT.

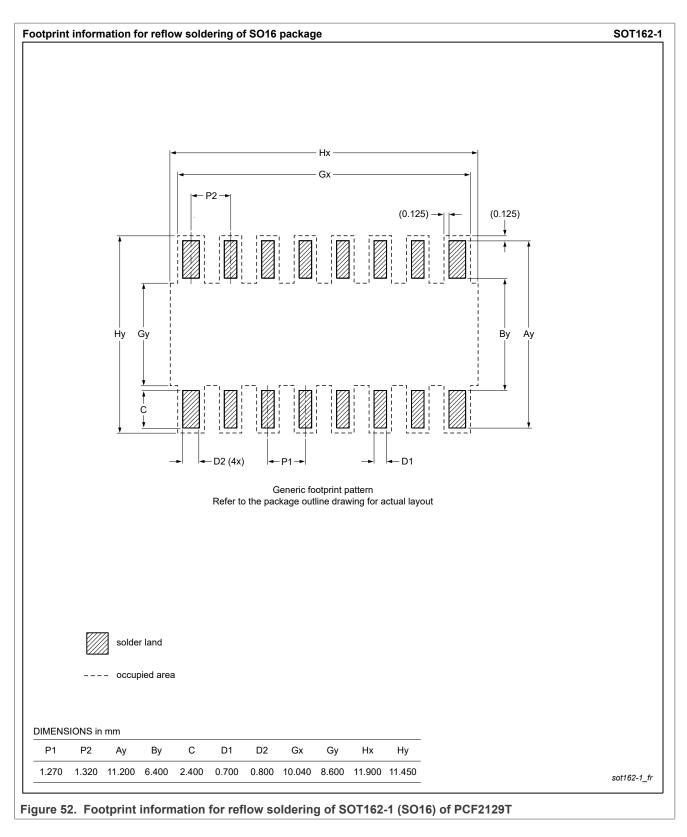
18 Soldering

For information about soldering, see [1].



18.1 Footprint information

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19 Appendix

PCF2129 Product data sheet

19.1 Real-Time Clock selection

Table 82.	Selection	n of Real-Time	Clocks	

Type name	Alarm, Timer, Watchdog	Interrupt output	Interface	I _{DD} , typical (nA)	Battery backup	Timestamp, tamper input	AEC-Q100 compliant	Special features	Packages
PCF8563	X	1	I ² C	250	-	-	-	-	SO8, TSSOP8, HVSON10
PCF8564A	Х	1	I ² C	250	-	-	-	integrated oscillator caps	WLCSP
PCA8565	x	1	I ² C	600	-	-	grade 1	high robustness, T _{amb} = -40 °C to 125 °C	TSSOP8, HVSON10
PCA8565A	x	1	I ² C	600	-	-	-	integrated oscillator caps, T _{amb} = -40 °C to 125 °C	WLCSP
PCF85063	-	1	I ² C	220	-	-	-	basic functions only, no alarm	HXSON8
PCF85063A	Х	1	l ² C	220	-	-	-	tiny package	SO8, DFN2626-10
PCF85063B	Х	1	SPI	220	-	-	-	tiny package	DFN2626-10
PCF85263A	X	2	I ² C	230	X	X	-	time stamp, battery backup, stopwatch $\frac{1}{100}$ s	SO8, TSSOP10, TSSOP8, DFN2626-10
PCF85263B	X	2	SPI	230	Х	X	-	time stamp, battery backup, stopwatch $\frac{1}{100}$ s	TSSOP10, DFN2626-10
PCF85363A	X	2	l ² C	230	X	X	-	time stamp, battery backup, stopwatch 1⁄ ₁₀₀ s, 64 Byte RAM	TSSOP10, DFN2626-10
PCF85363B	X	2	SPI	230	X	x	-	time stamp, battery backup, stopwatch 1/ ₁₀₀ s, 64 Byte RAM	TSSOP10, DFN2626-10
PCF8523	X	2	I ² C	150	Х	-	-	lowest power 150 nA in operation, FM+ 1 MHz	SO8, HVSON8, TSSOP14, WLCSP
PCF2123	X	1	SPI	100	-	-	-	lowest power 100 nA in operation	TSSOP14, HVQFN16
PCF2127	X	1	I ² C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated, 512 Byte RAM	SO16
PCF2127A	X	1	I ² C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated, 512 Byte RAM	SO20

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Table 82. Selection of Real-Time Clocks...continued

Type name	Alarm, Timer, Watchdog	Interrupt output	Interface	I _{DD} , typical (nA)	Battery backup	Timestamp, tamper input	AEC-Q100 compliant	Special features	Packages
PCF2129	X	1	I ² C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated	SO16
PCF2129A	X	1	I ² C and SPI	500	X	X	-	temperature compensated, quartz built in, calibrated	SO20
PCA2129	X	1	I ² C and SPI	500	X	X	grade 3	temperature compensated, quartz built in, calibrated	SO16
PCA21125	X	1	SPI	820	-	-	grade 1	high robustness, T _{amb} = -40 °C to 125 °C	TSSOP14

20 Abbreviations

Table 83. Abbre	eviations
Acronym	Description
AM	Ante Meridiem
BCD	Binary Coded Decimal
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DC	Direct Current
GPS	Global Positioning System
НВМ	Human Body Model
I ² C	Inter-Integrated Circuit
IC	Integrated Circuit
LSB	Least Significant Bit
MCU	Microcontroller Unit
ММ	Machine Model
MSB	Most Significant Bit
PM	Post Meridiem
POR	Power-On Reset
PORO	Power-On Reset Override
PPM	Parts Per Million
RC	Resistance-Capacitance
RTC	Real-Time Clock
SCL	Serial CLock line
SDA	Serial DAta line
SPI	Serial Peripheral Interface
SRAM	Static Random Access Memory
тсхо	Temperature Compensated Xtal Oscillator
Xtal	crystal

21 References

- [1] AN11186 Application and soldering information for the PCA2129 and PCF2129 TCXO RTC
- [2] JESD22-A114 Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)
- [3] JESD22-C101 Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components
- [4] JESD78 IC Latch-Up Test
- [5] SOT162-1_518 SO16; Reel pack; SMD, 13", packing information

- [6] SOT163-1_518 SO20; Reel pack; SMD, 13", packing information
- [7] UM10204 $\overline{I^2}$ C-bus specification and user manual
- [8] UM10569 Store and transport requirements

22 Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCF2129 v.8	20220718	Product data sheet	-	PCF2129 v.7
Modifications:	Added UL certUpdated layou	ification information t of <u>Section 4</u>		
PCF2129 v.7	20141219	Product data sheet	-	PCF2129AT v.6 PCF2129T v.4
PCF2129AT	I			I
PCF2127AT v.6	20130711	Product data sheet	-	PCF2127AT v.5
PCF2129AT v.5	20130212	Product data sheet	-	PCF2129AT v.4
PCF2129AT v.4	20121107	Product data sheet	-	PCF2129AT v.3
PCF2129AT v.3	20121004	Product data sheet	-	PCF2129AT v.2
PCF2129AT v.2	20100507	Product data sheet	-	PCF2129AT v.1
PCF2129AT v.1	20100113	Product data sheet	-	-
PCF2129T	·		·	,
PCF2129T v.4	20130711	Product data sheet	-	PCF2129T v.3
PCF2129T v.3	20130212	Product data sheet	-	PCF2129T v.2
PCF2129T v.2	20121025	Product data sheet	-	PCF2129T v.1
PCF2129T v.1	20120618	Product data sheet	-	-

23 Legal information

23.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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